



十速

TM57FA40/40A

DATA SHEET

Rev 2.3

tenx reserves the right to change or discontinue the manual and online documentation to this product herein to improve reliability, function or design without further notice. Tenx does not assume any liability arising out of the application or use of any product or circuit described herein; neither does it convey any license under its patent rights nor the rights of others. Tenx products are not designed, intended, or authorized for use in life support appliances, devices, or systems. If Buyer purchases or uses tenx products for any such unintended or unauthorized application, Buyer shall indemnify and hold tenx and its officers, employees, subsidiaries, affiliates and distributors harmless against all claims, cost, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use even if such claim alleges that tenx was negligent regarding the design or manufacture of the part.

AMENDMENT HISTORY

Version	Date	Description
V1.0	May, 2009	New release
V1.1	Sept, 2009	<ol style="list-style-type: none"> 1. Modify system clock mode for fast crystal 455 KHz ~ 12 MHz. 2. Add 8 DIP/SOP in packet types in Features section. 3. Add 8 SOP, 8 DIP figure in Pin Assignment section. 4. In SYSCFG section, bit 11-10, for 01 setting, modify the LVR threshold to 2.9V. 5. In SYSCFG section, bit 9-8, modify the Fast crystal to 455 KHz ~ 12 MHz. 6. Modify CLRWDT description to Clear Watchdog/Wakeup Timer. 7. Add the figures in Clock Timing in Electrical Characteristics section. 8. Add figures for 8-DIP and 8-SOP Package Dimension.
V1.2	Jan, 2010	<ol style="list-style-type: none"> 1. Remove 8 DIP/SOP in packet types in Features section. 2. Remove 8 SOP, 8 DIP figures in Pin Assignment section. 3. Modify the default of nPAPU, nPBPU, nPDPU in R-Plane. 4. Modify GOTO / CALL range to 0xFFFF. 5. Modify the Operating temperature becomes -40 to +85°C. 6. Modify the temperature in clock timing in Electrical Characteristics section becomes -40 to +85°C. 7. Add FSR.7 fixed 0 in F-Plane. 8. Modify PA1 set by rising/falling edge.
V1.3	Dec, 2010	<ol style="list-style-type: none"> 1. Add more description about /Borrow and /Digit Borrow in ALU and Working (W) Register section. 2. Add Internal RC mode description and figure in System Clock Oscillator section. 3. Modify the equation of the frequency calculation in Buzzer Output section. 4. Modify the system block diagram. 5. Modify the ordering information.
V1.4	Oct, 2011	<ol style="list-style-type: none"> 1. Modify the package type data. 2. Add description about LVR selection in Reset Section. 3. Modify the data in DC Characteristics.
V1.5	Dec, 2011	Add Ordering Information table in the Packaging Information section.
V1.6	Jan, 2012	Modify Ordering Information table in the Packaging Information section.
V1.7	Jan, 2012	<ol style="list-style-type: none"> 1. Add the Electrical Characteristics specs in the Features section. 2. Add description in Reset section. 3. Merge the information about LVR Circuit Characteristics into DC Characteristics table. 4. Modify the Low Voltage Detection Time data in Reset Timing Characteristics.
V1.8	Apr, 2012	<ol style="list-style-type: none"> 1. Modify the document, add serial number for TM57FA40A. 2. Add description in Features section about the system clock mode and power on reset. 3. Modify figures in the Pin Assignment section.

		<ol style="list-style-type: none"> 4. Modify the description in Interrupt section. 5. Modify the description in Reset section. 6. Modify the SYSCFG table. 7. Add output high/low current in DC Characteristics section. 8. Add description for TM57FA40A about power supply current in DC Characteristics section. 9. Add description for TM57FA40A in the ordering information.
V1.9	Jul, 2012	Modify Absolute Maximum Ratings data in Electrical Characteristics section.
V2.0	Jun, 2013	<ol style="list-style-type: none"> 1. Add supported EV board on ICE. 2. Add Pin Summary. 3. Modify Ordering Information.
V2.1	Aug, 2013	Modify Ordering Information.
V2.2	Feb, 2015	Modify Pin Assignment.
V2.3	Aug, 2018	Add SOP/DIP8 information

CONTENTS

AMENDMENT HISTORY	2
FEATURES	6
BLOCK DIAGRAM	7
PIN ASSIGNMENT	8
PIN DESCRIPTION	9
PIN SUMMARY	10
FUNCTIONAL DESCRIPTION	11
1. CPU Core	11
1.1 Clock Scheme and Instruction Cycle	11
1.2 Addressing Mode	12
1.3 Programming Counter (PC) and Stack.....	12
1.4 ALU and Working (W) Register	13
1.5 STATUS Register	13
1.6 Interrupt.....	14
2. Chip Operation Mode	15
2.1 Reset.....	15
2.2 System Configuration Register (SYSCFG)	16
2.3 FLASH Program ROM	17
2.4 Power-Down Mode	17
3. Peripheral Functional Block	18
3.1 Watchdog (WDT) / Wakeup (WKT) Timer.....	18
3.2 Timer0: 8-bit Timer/Counter with Pre-scale (PSC)	19
3.3 Timer1: 8-bit Timer with Pre-scale (PSC)	20
3.4 8+2 bit PWM.....	22
3.5 12-bit ADC.....	24
3.6 System Clock Oscillator.....	26
3.7 BUZZER Output	27
4. I/O Port	29
4.1 PA0-2	29
4.2 PA3-6, PB0-1, PD0-7.....	30
4.3 PA7.....	31
MEMORY MAP	32
F-Plane	32
R-Plane	33
INSTRUCTION SET	35

ELECTRICAL CHARACTERISTICS	47
1. Absolute Maximum Ratings.....	47
2. DC Characteristics	48
3. Clock Timing	49
4. Reset Timing Characteristics	50
5. ADC Electrical Characteristics.....	50
PACKAGING INFORMATION	51
20-DIP Package Dimension	52
20-SOP Package Dimension	53
16-DIP Package Dimension	54
16-SOP Package Dimension	55
8-DIP (300mil) Package Dimension	56
8-SOP (150mil) Package Dimension	57

FEATURES

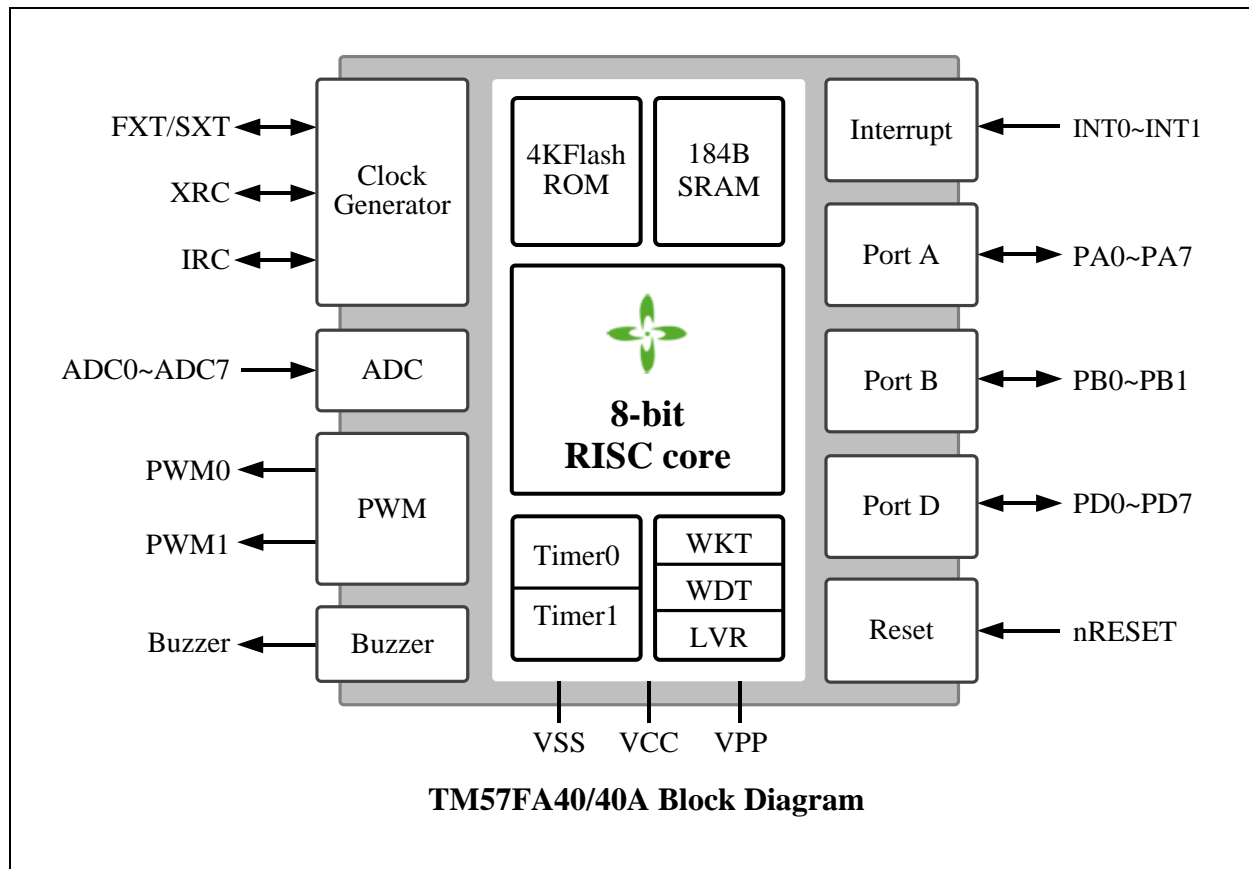
1. ROM: 4K x 14 bits Flash ROM
2. RAM: 184 x 8 bits
3. STACK: 6 Levels
4. I/O ports: Three Programmable I/O ports (Max. 18 pins)
5. Timer0/Counter: 8-bit timer/counter with divided by 1~256 pre-scale option
6. Timer1: 8-bit auto-reloadable timer with divided by 1~256 pre-scale option
7. Two 8+2 bit PWM channels capable of 1024 duty resolution
8. 12-bit ADC with 8 channels input
9. Buzzer output
10. Watchdog/Wakeup Timer: On chip Timer based on internal RC oscillation, 11~132 ms wakeup time
11. Reset: Power On Reset, Watchdog Reset, Low Voltage Reset, External pin Reset
12. System Clock Mode:
 - Slow Crystal (SXT): 32 KHz
 - Fast Crystal (FXT): 455 KHz ~12 MHz
 - Internal RC (IRC): 4 MHz
 - External RC (XRC)
13. 2-Level Low Voltage Reset: 2.1V/2.9V (Can be disabled)
14. Operation Voltage: Low Voltage Reset Level to 5.5V
 - fosc = 4 MHz, 2.4V ~ 5.5V
 - fosc = 8 MHz, 2.4V ~ 5.5V
 - fosc = 12 MHz, 3.0V ~ 5.5V
15. Instruction set: 36 Instructions
16. Interrupts: Three pin interrupts, Timer0/Timer1 interrupt and Wakeup Timer interrupt
17. Power Down mode support
18. Package Types: 8-DIP/SOP, 16-DIP/SOP, 20-DIP/SOP

Device	Icc in Stop Mode	Note
TM57FA40	0.1 uA@2.2~5V	Power-on Reset disable in Stop mode
TM57FA40A	3 uA@3V, 5 uA@5V	Power-on Reset enable in Stop mode

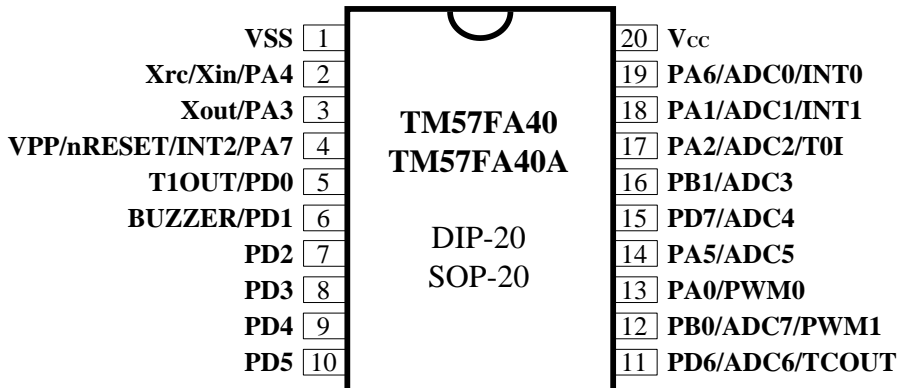
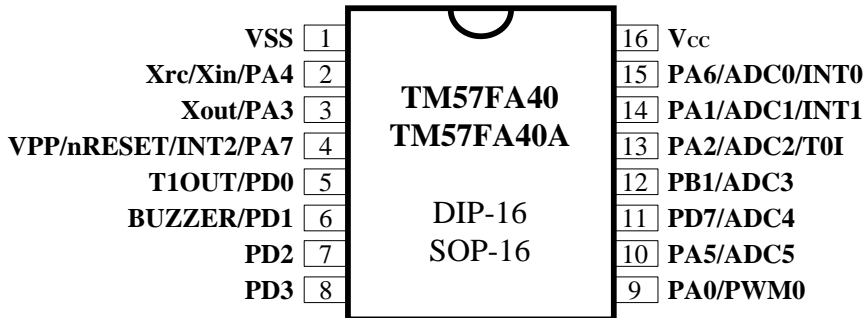
19. Supported EV board on ICE

EV board: EV2795

BLOCK DIAGRAM



PIN ASSIGNMENT



PIN DESCRIPTION

Name	In/Out	Pin Description
PA2-PA0	I/O	Bit-programmable I/O port for Schmitt-trigger input, CMOS “ push-pull ” output or “ pseudo-open-drain ” output. Pull-up resistors are assignable by software.
PA6-PA3 PB1-PB0 PD7-PD0	I/O	Bit-programmable I/O port for Schmitt-trigger input, CMOS “ push-pull ” output or “ open-drain ” output. Pull-up resistors are assignable by software.
PA7	I	Schmitt-trigger input
nRESET	I	External active low reset
Xin, Xout	-	Crystal/Resonator oscillator connection for system clock
Xrc		External RC oscillator connection for system clock
VCC, VSS	P	Power input pin and ground
VPP	I	PROM programming high voltage input
INT0~2	I	External interrupt input
T0I	I	Timer0’s input in counter mode
T1OUT	O	Timer1 match output, T1OUT toggles when Timer1 overflow occurs.
BUZZER	O	BUZZER output
TCOUT	O	Instruction cycle clock divided by N output. Where N is 1, 2, 4, 8. The instruction clock frequency is system clock frequency divided by two.
PWM0/PWM1	O	10-bit PWM output
ADC7~0	I	A/D channels input

PIN SUMMARY

Pin Number		Pin Name	Type	GPIO					Function After Reset	Alternate Function			
20-SOP/DIP	16-SOP/DIP			Input		Output				PWM	Touch Key	ADC	MISC
				Weak Pull-up	Ext. Interrupt	O.D	P.O.D	P.P					
1	1	VSS	P										
2	2	Xrc/Xin/PA4	I/O	○		○		○	SYS				
3	3	Xout/PA3	I/O	○		○		○	SYS				
4	4	VPP/nRESET/INT2/PA7	I	○	○				SYS				nRESET
5	5	T1OUT/PD0	I/O	○		○		○	PD0				T1OUT
6	6	BUZZER/PD1	I/O	○		○		○	PD1				BUZZER
7	7	PD2	I/O	○		○		○	PD2				
8	8	PD3	I/O	○		○		○	PD3				
9	-	PD4	I/O	○		○		○	PD4				
10	-	PD5	I/O	○		○		○	PD5				
11	-	PD6/ADC6/TCOUT	I/O	○		○		○	PD6			○	TCOUT
12	-	PB0/ADC7/PWM1	I/O	○		○		○	PB0	○		○	
13	9	PA0/PWM0	I/O	○			○	○	PA0	○			
14	10	PA5/ADC5	I/O	○		○		○	PA5			○	
15	11	PD7/ADC4	I/O	○		○		○	PD7			○	
16	12	PB1/ADC3	I/O	○		○		○	PB1			○	
17	13	PA2/ADC2/TOI	I/O	○			○	○	PA2			○	TOI
18	14	PA1/ADC1/INT1	I/O	○	○		○	○	PA1			○	
19	15	PA6/ADC0/INT0	I/O	○	○	○		○	PA6			○	
20	16	VCC	P										

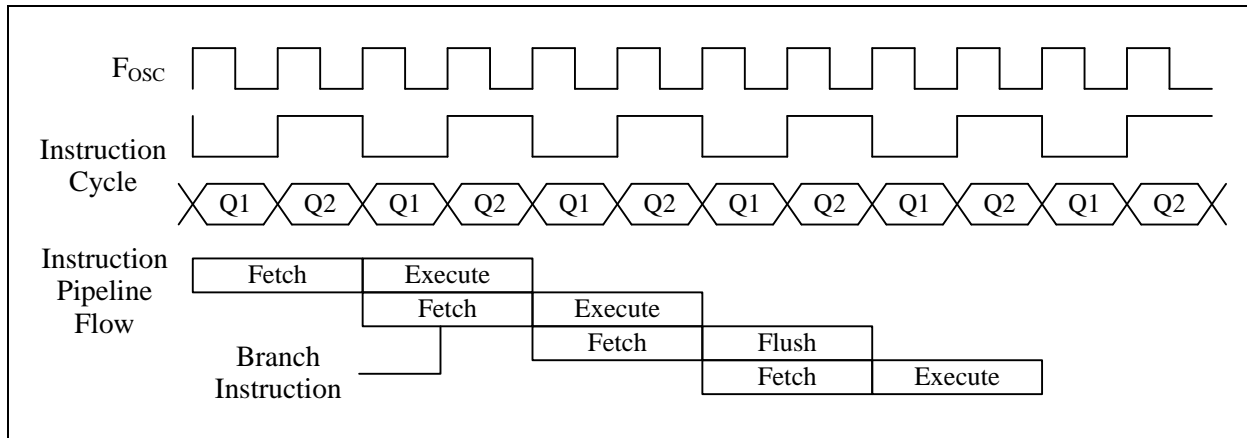
Symbol : P.P. = Push-Pull Output
P.O.D. = Pseudo Open Drain
O.D. = Open Drain
SYS = by SYSCFG bit

FUNCTIONAL DESCRIPTION

1. CPU Core

1.1 Clock Scheme and Instruction Cycle

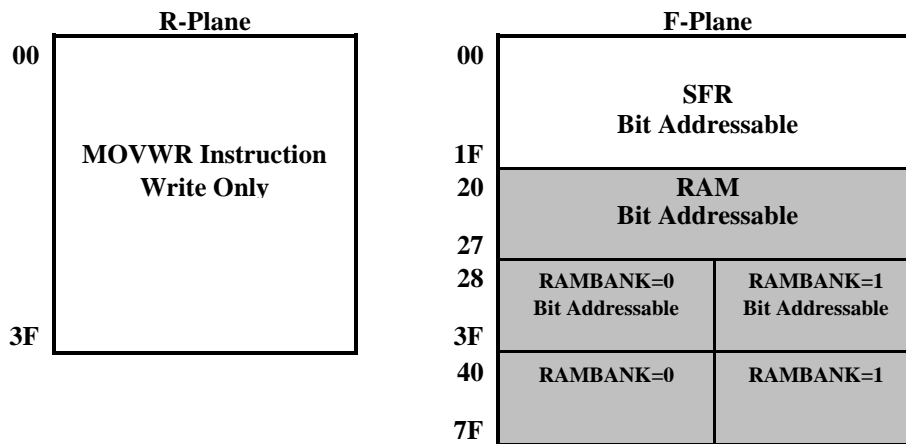
The system clock is internally divided by two to generate Q1 state and Q2 state for each instruction cycle. The Programming Counter (PC) is updated at Q1 and the instruction is fetched from program ROM and latched into the instruction register in Q2. It is then decoded and executed during the following Q1-Q2 cycle. Branch instructions take two cycles since the fetch instruction is ‘flushed’ from the pipeline, while the new instruction is being fetched and then executed.



1.2 Addressing Mode

There are two Data Memory Planes in CPU, R-Plane and F-Plane. The registers in R-Plane are write-only. The “MOVWR” instruction copy the W-register’s content to R-Plane registers by direct addressing mode.

The lower locations of F-Plane are reserved for the SFR. Above the SFR is General Purpose Data Memory, implemented as static RAM. F-Plane can be addressed directly or indirectly. Indirect Addressing is made by INDF register. The INDF register is not a physical register. Addressing INDF actually addresses the register whose address contains in the FSR register (FSR is a pointer). The first half of F-Plane is bit-addressable, while the second half of F-Plane is not bit-addressable.



1.3 Programming Counter (PC) and Stack

The Programming Counter is 12-bit wide capable of addressing a 4K x 14 program ROM. As a program instruction is executed, the PC will contain the address of the next program instruction to be executed. The PC value is normally increased by one except the followings.

The Reset Vector (000h) and the Interrupt Vector (001h) are provided for PC initialization and Interrupt. For CALL/GOTO instructions, PC loads 12 bits address from instruction word. For RET/RETI/RETLW instructions, PC retrieves its content from the top level STACK. For the other instructions updating PC [7:0], the PC [11:8] keeps unchanged. The STACK is 12-bit wide and 6-level in depth. The CALL instruction and Hardware interrupt will push STACK level in order. While the RET/RETI/RETLW instruction pops the STACK level in order.

1.4 ALU and Working (W) Register

The ALU is 8-bit wide and capable of addition, subtraction, shift and logical operations. In two-operand instructions, typically one operand is the W register, which is an 8-bit non-addressable register used for ALU operations. The other operand is either a file register or an immediate constant. In single operand instructions, the operand is either W register or a file register. Depending on the instruction executed, the ALU may affect the values of Carry (C), Digit Carry (DC), and Zero (Z) Flags in the STATUS register. The C and DC flags operate as a /Borrow and /Digit Borrow, respectively, in subtraction.

Note: /Borrow represents inverted of Borrow register.

/Digit Borrow represents inverted of Digit Borrow register.

1.5 STATUS Register

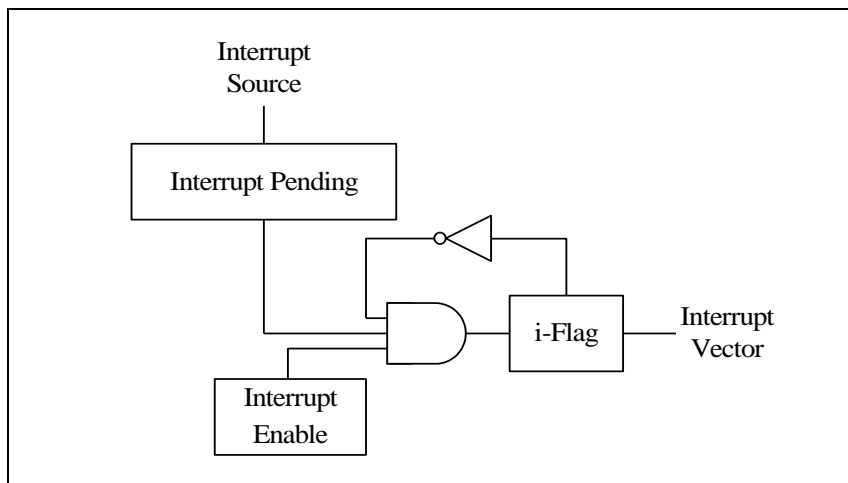
This register contains the arithmetic status of ALU and the Reset status. The STATUS register can be the destination for any instruction, as with any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. It is recommended, therefore, that only BCF, BSF and MOVWF instructions are used to alter the STATUS Register because these instructions do not affect those bits.

STATUS	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Reset Value	–	–	0	0	0	0	0	0
R/W	–	–	R/W	R	R	R/W	R/W	R/W
Bit	Description							
7-6	Not Used							
5	RAMBANK: RAM Bank Selection 0: RAM Bank0 1: RAM Bank1							
4	TO: Time Out 0: after Power On Reset, LVR Reset, or CLRWDT/SLEEP instruction 1: WDT time out occurs							
3	PD: Power Down 0: after Power On Reset, LVR Reset, or CLRWDT instruction 1: after SLEEP instruction							
2	Z: Zero Flag 0: the result of a logic operation is not zero 1: the result of a logic operation is zero							
1	DC: Decimal Carry Flag or Decimal/Borrow Flag							
	ADD instruction				SUB instruction			
	1: a carry from the low nibble bits of the result occurs 0: no carry				1: no borrow 0: a borrow from the low nibble bits of the result occurs			
0	C: Carry Flag or Borrow Flag							
	ADD instruction				SUB instruction			
	1: a carry occurs from the MSB 0: no carry				1: no borrow 0: a borrow occurs from the MSB			

1.6 Interrupt

The device has 1 level, 1 vector and six interrupt sources. Each interrupt source has its own enable control bit. An interrupt event will set its individual pending flag, no matter its interrupt enable control bit is 0 or 1. Because device has only 1 vector, there is not an interrupt priority register. The interrupt priority is determined by F/W.

If the corresponding interrupt enable bit has been set (INTE), it would trigger CPU to service the interrupt. CPU accepts interrupt in the end of current executed instruction cycle. In the mean while, a “CALL 001” instruction is inserted to CPU, and i-flag is set to prevent recursive interrupt nesting. The i-flag is cleared in the instruction after the “RETI” instruction. That is, at least one instruction in main program is executed before service the pending interrupt. The interrupt event is level triggered. F/W must clear the interrupt event register while serving the interrupt routine.



2. Chip Operation Mode

2.1 Reset

The device can be RESET in four ways.

- Power-On-Reset
- Low Voltage Reset (LVR)
- External Pin Reset (PA7)
- Watchdog Reset (WDT)

After Power-On-Reset, all system and peripheral control registers are then set to their default hardware Reset values. The clock source, LVR level and chip operation mode are selected by the SYSCFG register value.

The Low Voltage Reset features static reset when supply voltage is below a threshold level. There are two threshold levels can be selected. The LVR's operation mode is defined by the SYSCFG register. There are two voltage selections for the LVR threshold level, one is higher level which is suitable for application with VCC is more than 3.3V, while another one is suitable for application with VCC is less than 3.3V.

See the following LVR Selection Table; user must also consider the lowest operating voltage of operating frequency.

LVR Selection Table:

LVR Threshold Level	Consider the operating voltage to choose LVR
LVR2.9	$5.5V > VCC > 3.3V$
LVR2.1	VCC is wide voltage range

The External Pin Reset and Watchdog Reset can be disabled or enabled by the SYSCFG register. These two resets also set all the control registers to their default reset value. The TO/PD flag is not affected by these resets.

2.2 System Configuration Register (SYSCFG)

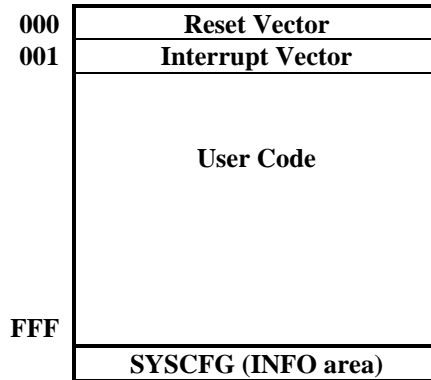
The System Configuration Register (SYSCFG) is located at Flash INFO area. The SYSCFG determines the option for initial condition of MCU. It is written by FLASH Writer only. User can select clock source, LVR threshold voltage and chip operation mode by SYSCFG register. The 13th bit of SYSCFG is code protection selection bit. If this bit is 1, the data in FLASH will be protected when user reads FLASH.

Bit	13~0	
Default Value	00_0000_000x_xxxx	
Bit	Description	
13	PROTECT: Code Protection Selection	
	1	Enable
	0	Disable
12	IVCPD: IVC*/LVR Power Down in Sleep mode	
	1	IVC/LVR OFF in Sleep mode
	0	IVC/LVR ON in Sleep mode
11-10	LVR: LV reset mode	
	11	2.1V, always enable
	10	Invalid
	01	2.9V, always enable
	00	LVR disable
9-8	CLK: Clock Source Selection	
	11	Fast Xtal (FXT) (455 KHz~12 MHz)
	10	Slow Xtal (SXT) (32 KHz)
	01	Internal RC (IRC) (4 MHz)
	00	External RC (XRC)
7	RESET: External pin Reset Enable	
	1	Enable External pin Reset
	0	Disable External pin Reset
6	WDT: WDT Reset Enable	
	1	Enable WDT Reset, Disable WKT Timer
	0	Disable WDT Reset, Enable WKT Timer
4-0	Reserved by tenx	

* IVC is the chip built-in 3.3V regulator for internal circuit.

2.3 FLASH Program ROM

The FLASH Program ROM of this device is 4K words, with an extra INFO area to store the SYSCFG. The FLASH ROM can be written multi-times and can be read as long as the PROTECT bit of SYSCFG is not set. The SYSCFG can be read no matter PROTECT is set or cleared, but can be written only when PROTECT is not set or FLASH ROM is erased. That is, un-protect the PROTECT bit needs the erased FLASH ROM.



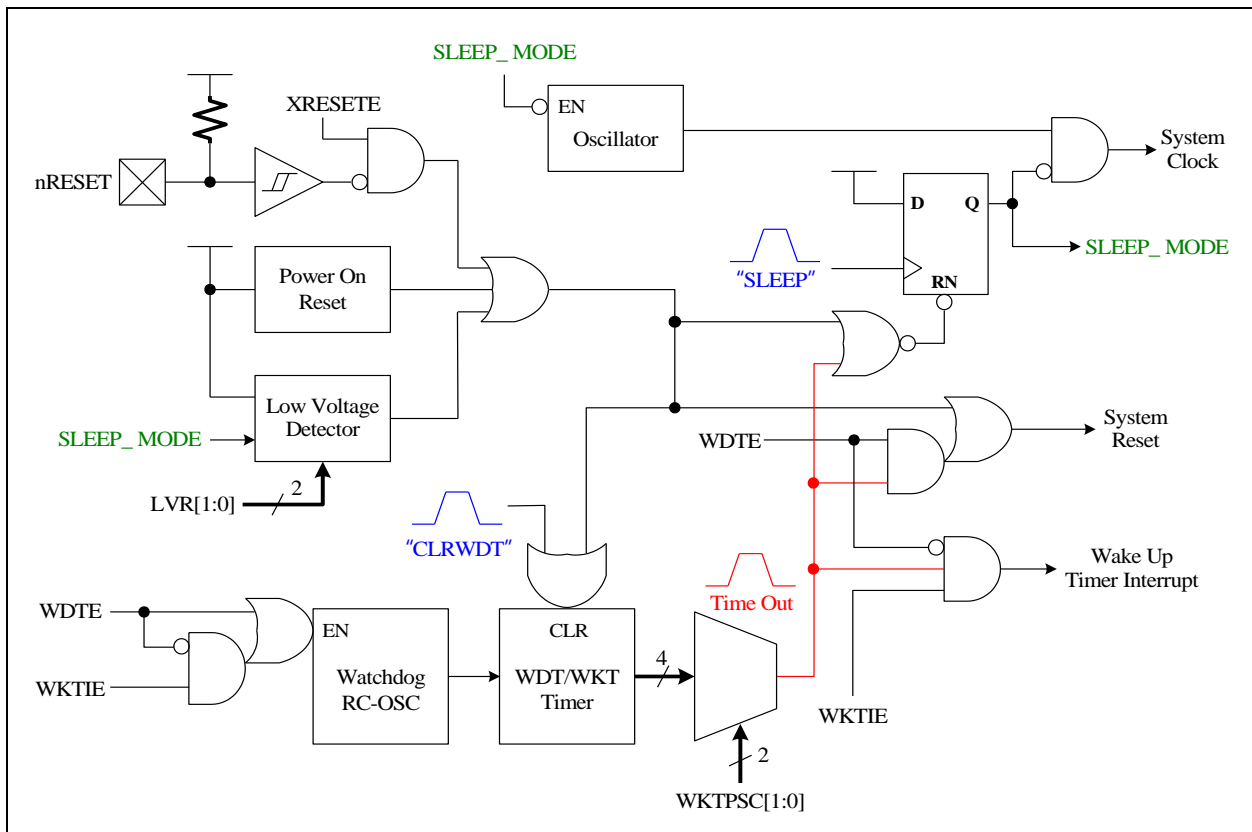
2.4 Power-Down Mode

The Power-down mode is activated by SLEEP instruction. During the Power-down mode, the system clock and peripherals stop to minimize power consumption, while the WDT/WKT Timer is working or not depends on F/W setting. The Power down mode can be terminated by Reset, or enabled Interrupts (External pins and WKT interrupt). In the power down mode, user can enable or disable IVC according to the standby current requirement. Enabled IVC can provide the chip internal circuit more stable 3.3V power.

3. Peripheral Functional Block

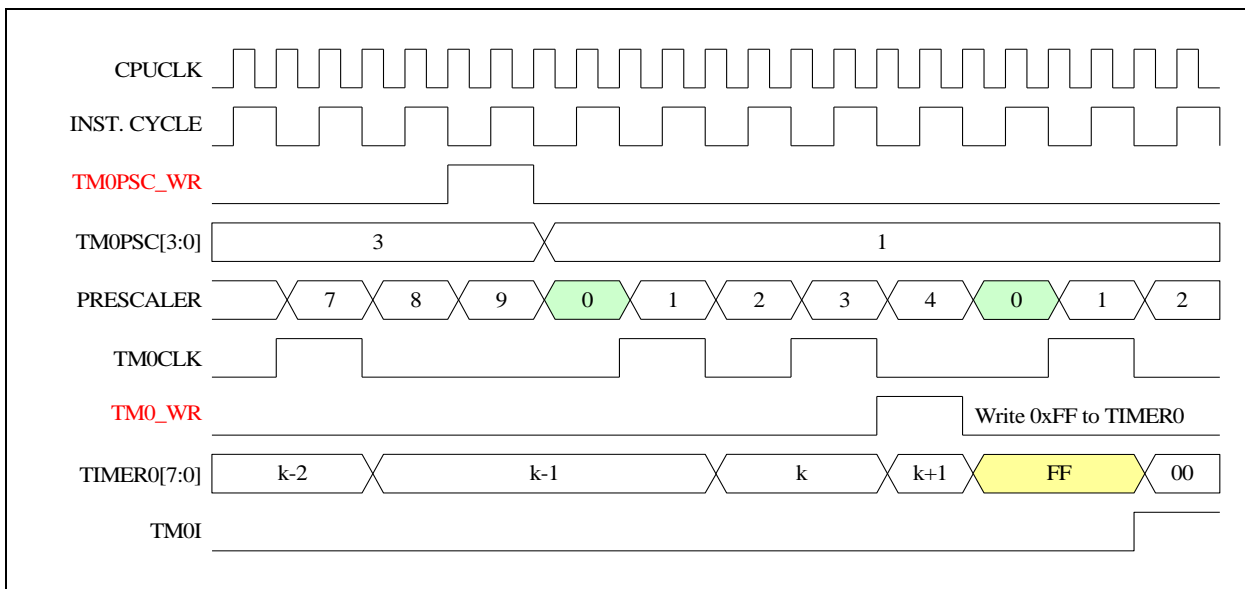
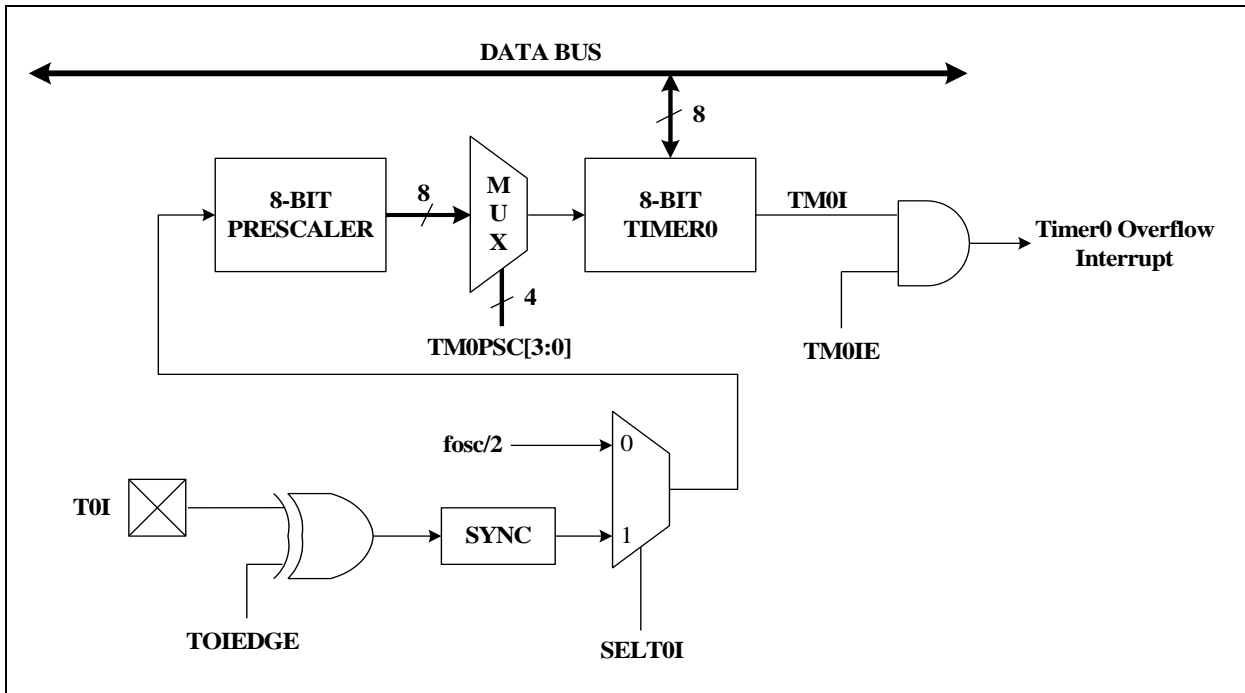
3.1 Watchdog (WDT) / Wakeup (WKT) Timer

The WDT and WKT share the same internal RC Timer. The overflow period of WDT/WKT can be selected from 11 ms to 132 ms. The WDT/WKT is cleared by the CLRWDT instruction. If the Watchdog Reset is enabled (WDTE=1), the WDT generates the chip reset signal, even in sleep mode, otherwise, the WKT only generates overflow time out interrupt. The WDT/WKT works in both normal mode and sleep mode. If WDTE=0 and WKTIE=0 (Wakeup interrupt disable), the internal RC Timer stops for power saving.



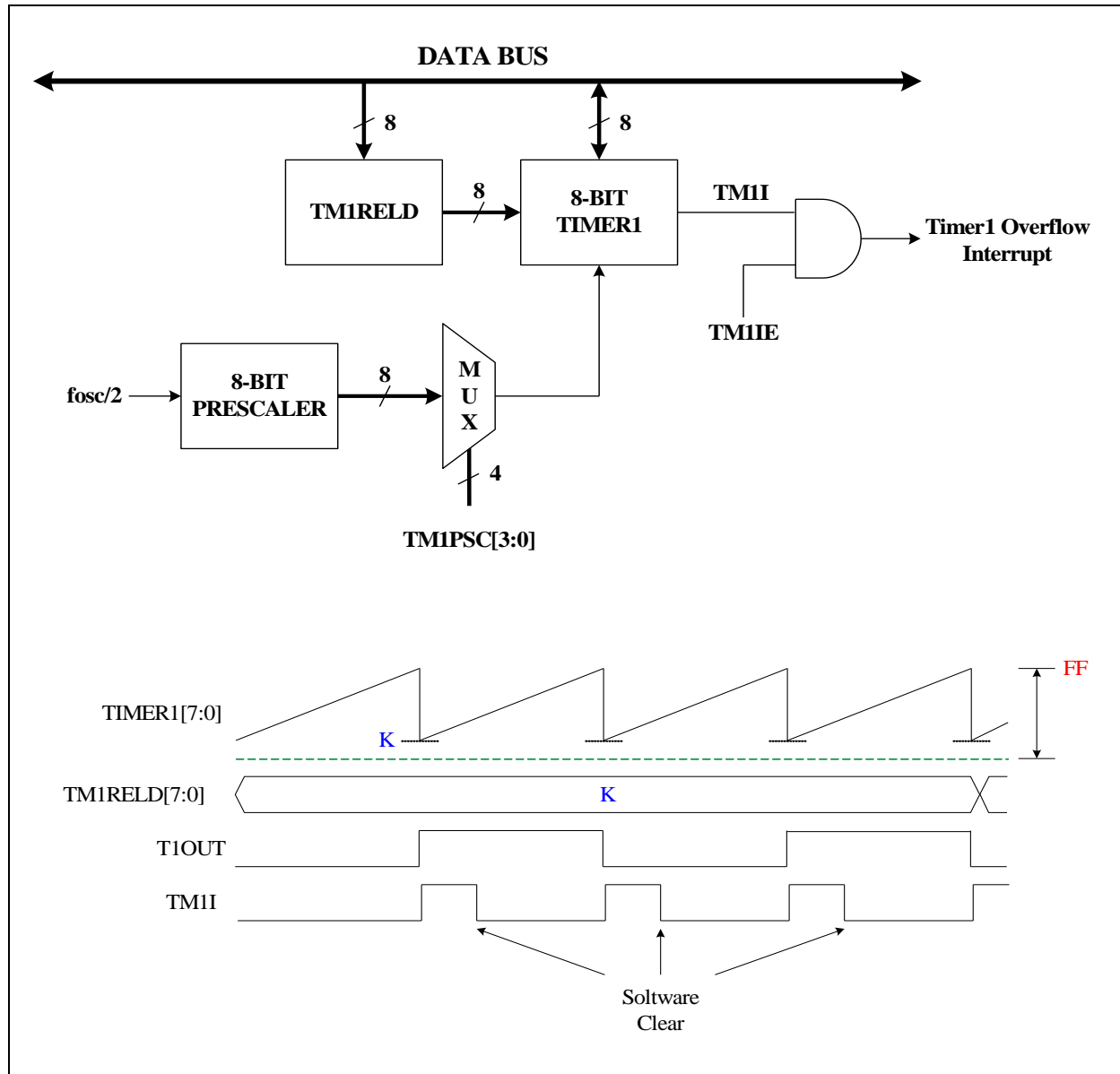
3.2 Timer0: 8-bit Timer/Counter with Pre-scale (PSC)

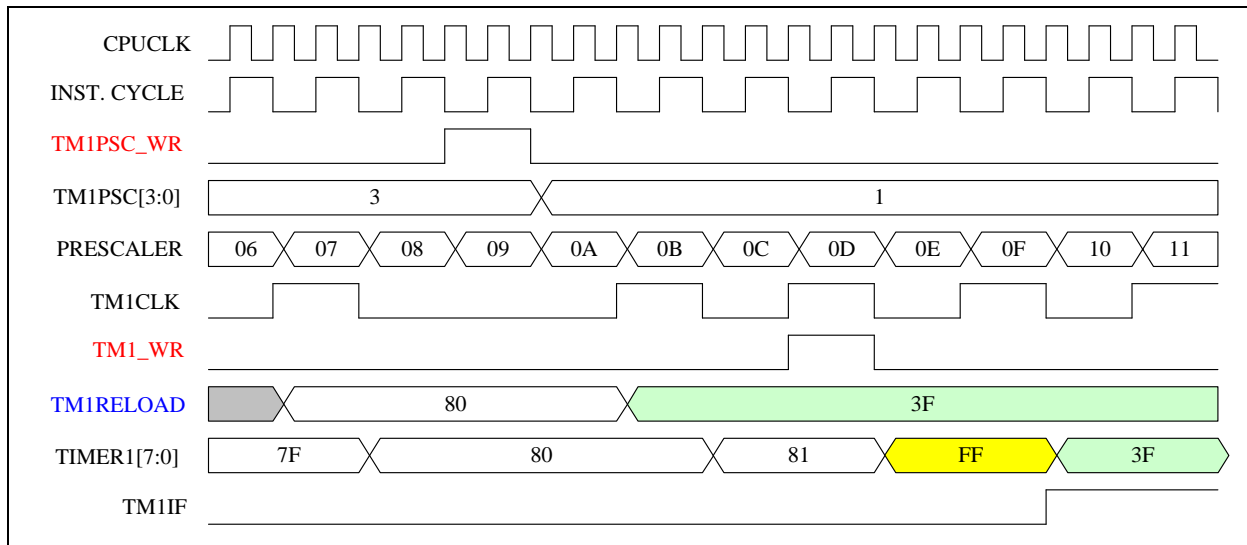
The Timer0 is an 8-bit wide register of F-Plane. It can be read or written as any other register of F-Plane. Besides, Timer0 increases itself periodically and automatically rolls over based on the pre-scaled clock source, which can be the instruction cycle or TOI input. The Timer0 increase rate is determined by “Timer0 Pre-Scale” (TM0PSC) register in R-Plane. The Timer0 can generate interrupt (TM0I) when it rolls over.



3.3 Timer1: 8-bit Timer with Pre-scale (PSC)

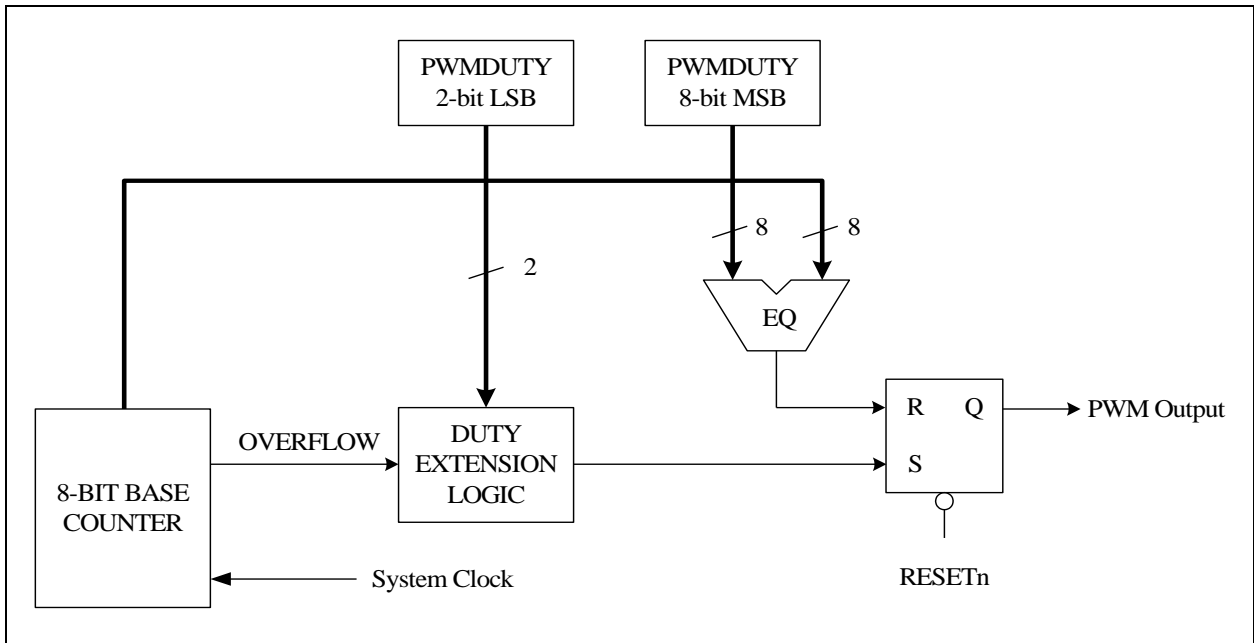
The Timer1 is an 8-bit wide register of F-Plane. It can be read or written as any other register of F-Plane. Besides, Timer1 increases itself periodically and automatically reloads a new “offset value” (TM1RELD) while it rolls over based on the pre-scaled instruction clock. The Timer1 increase rate is determined by “Timer1 Pre-Scale” (TM1PSC) register in R-Plane. The Timer1 can generate interrupt (TM1I) and T1OUT toggle signal when it rolls over.

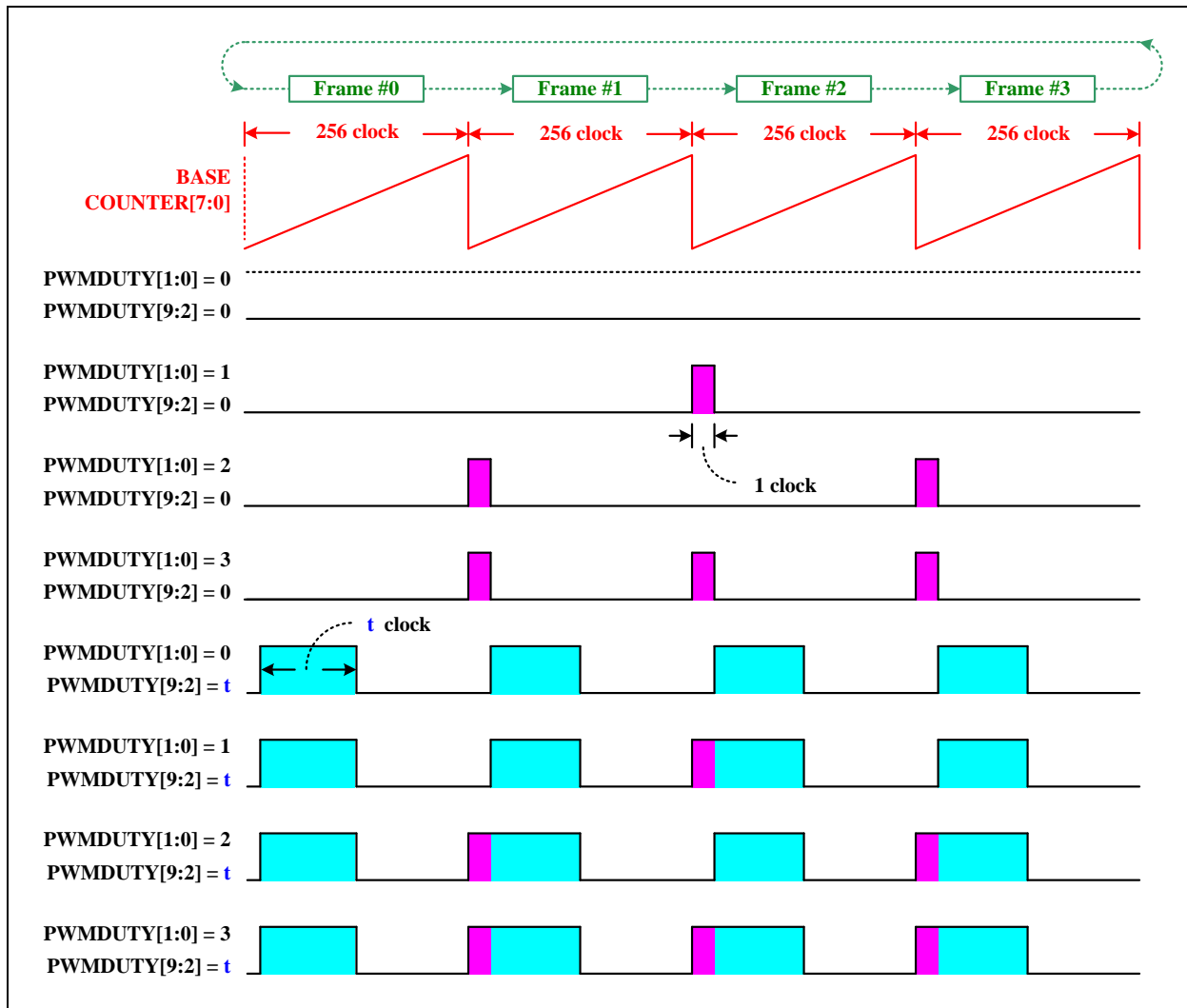




3.4 8+2 bit PWM

PWM0 and PWM1 have the same structure. The PWM can generate fix frequency waveform with 1024 duty resolution based on System Clock. A spread LSB technique allows PWM to run its frequency at “System Clock divided by 256” instead of “System Clock divided by 1024”, which means the PWM is 4 times faster than normal. The advantage of higher PWM frequency is that the post RC filter can transform the PWM signal to more stable DC voltage level. The PWM output signal reset to low level whenever the 8-bit base counter matches the 8-bit MSB of PWM duty register (PWMDUTY). When the base counter rolls over, the 2-bit LSB of PWM duty register decide whether to set the PWM output signal high immediately or set it high after one clock cycle delay.



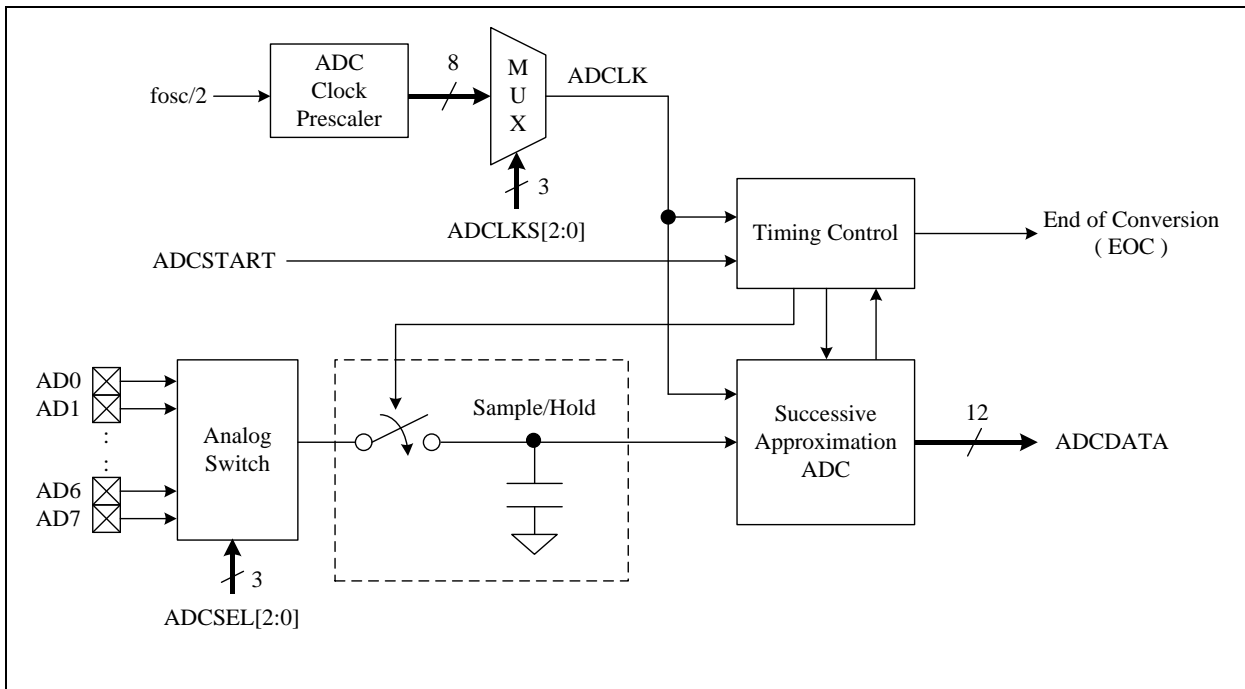


PWM example code:

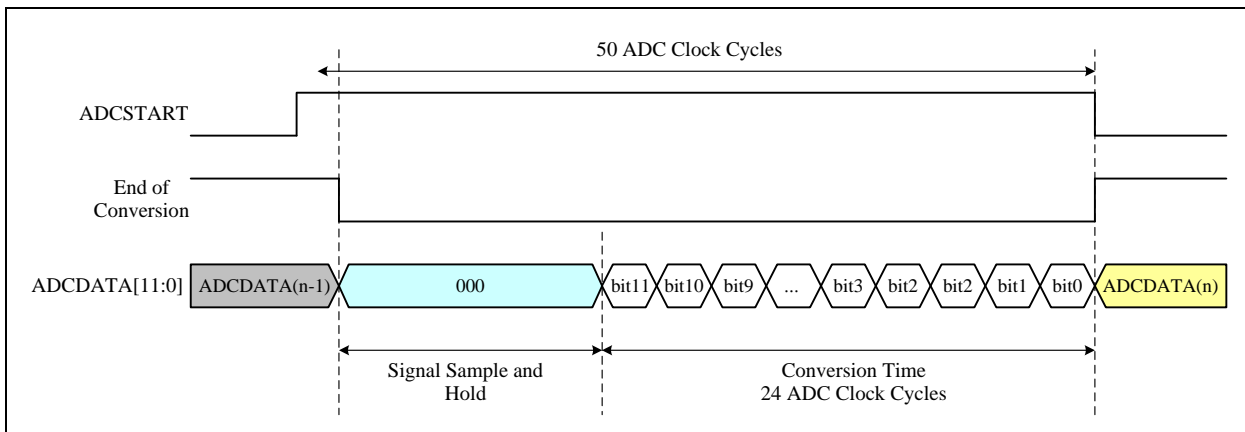
```

movlw    01111111b
movwf    0ch           ;set PWM0DUTY[9:2]=8'b01111111
movlw    11000000b
movwf    0dh           ;set PWM0DUTY[1:0]=2'b11
movlw    01000000b
movwr    0bh           ;enable PWM0 output to PA0 (PWM0_OUT)
:
:
movlw    00h
movwr    0bh           ;disable PWM0 (PWM0_OUT)
    
```

3.5 12-bit ADC



The 12-bit ADC (Analog to Digital Converter) consists of an 8-channel analog input multiplexer, control register, clock generator, 12-bit successive approximation register, and output data register. To use the ADC, user needs to set ADCLKS to choose a proper ADC clock frequency, which must be less than 2 MHz. User then launches the ADC conversion by setting the ADCSTART control bit. After end of conversion, H/W automatically clears the ADCSTAT bit. User can poll this bit to know the conversion status. The nADC_IE control register is used for ADC pin type setting, user can write the corresponding bit to “0” when the pin is used as an ADC input. The setting can disable the pin logical input path to save power consumption.



ADC example code:

```
    movlw    00000111b
    movwf    11h          ;ADC channel select,ADC7(PB0) (ADCSEL)

    movlw    00000001h
    movwr    09h          ;disable PB0 pull up resistor    (nPBPUP)

    movlw    01111111b
    movwr    12h          ;set ADC7 input enable (nADC_IE)

    movlw    00010000b
    movwr    0ch          ;set ADC clock is instruction cycle / 64 (ADCCLKS)

    bsf      11h,3        ;start  ADC conversion (ADCSTART)
```

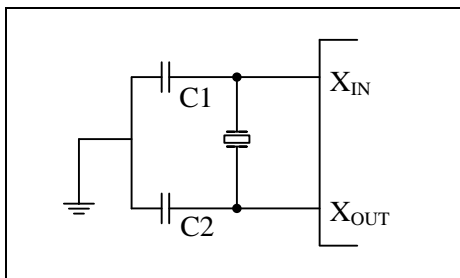
ADC_LOOP:

```
    btfsc    11h,3
    goto     ADC_LOOP    ;wait ADCSTART go LOW

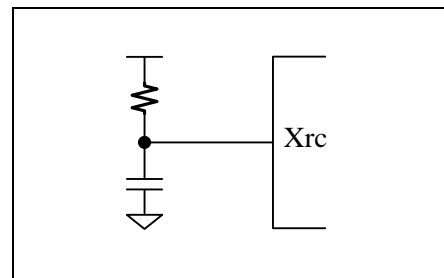
    :
    :
    :                    ;read ADCQ[11:0] (ADCDQ)
```

3.6 System Clock Oscillator

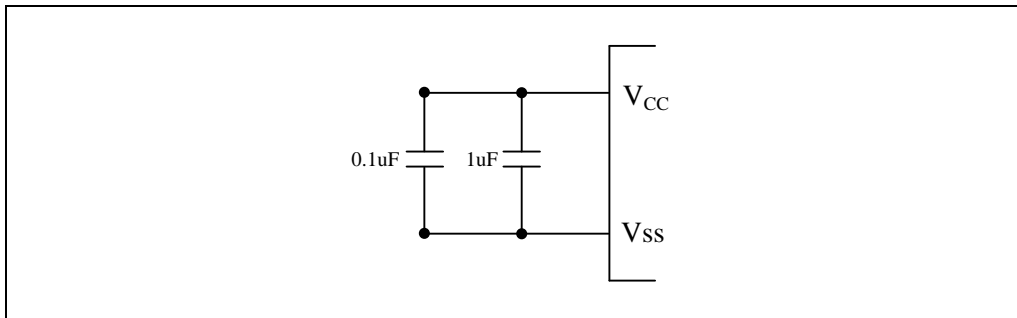
System Clock can be operated in four different oscillation modes, which is selected by setting the CLKS in the SYSCFG register. In Slow/Fast Crystal mode, a crystal or ceramic resonator is connected to the X_{IN} and X_{OUT} pins to establish oscillation. In external RC mode, the external resistor and capacitor determine the oscillation frequency. In the internal RC mode, the on chip oscillator generates 4 MHz system clock. In this mode, PCB Layout may have strong effect on the stability of Internal Clock Oscillator. Since power noise degrades the performance of Internal Clock Oscillator, placing power supply bypass capacitors 1 uF and 0.1 uF very close to V_{CC}/V_{SS} pins improves the stability of clock and the overall system.



External Oscillator Circuit
(Crystal or Ceramic)



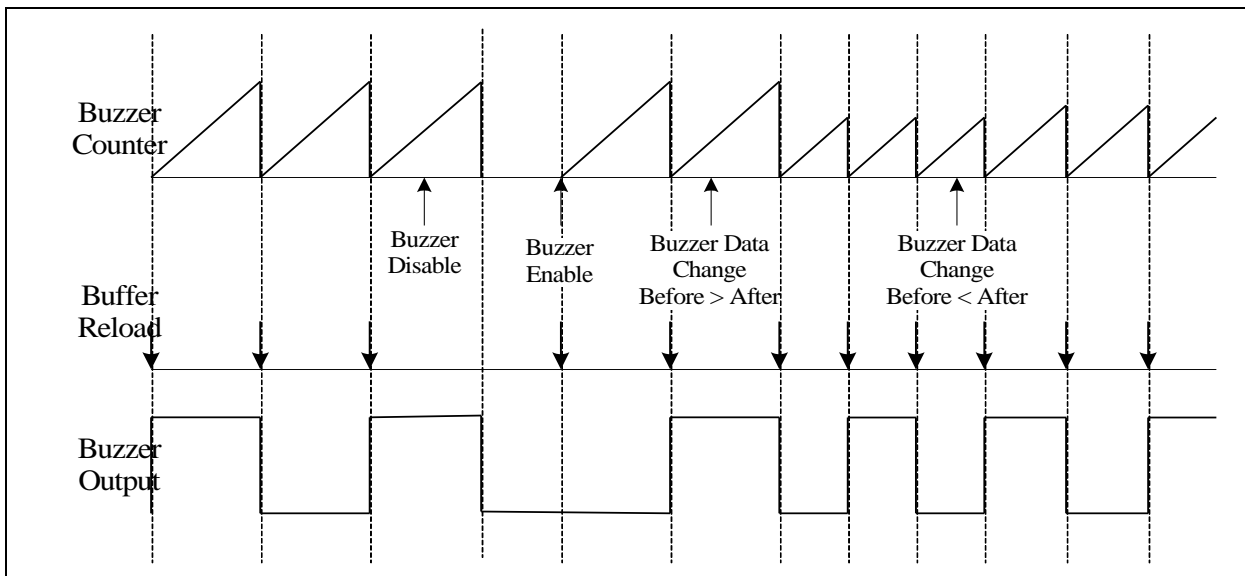
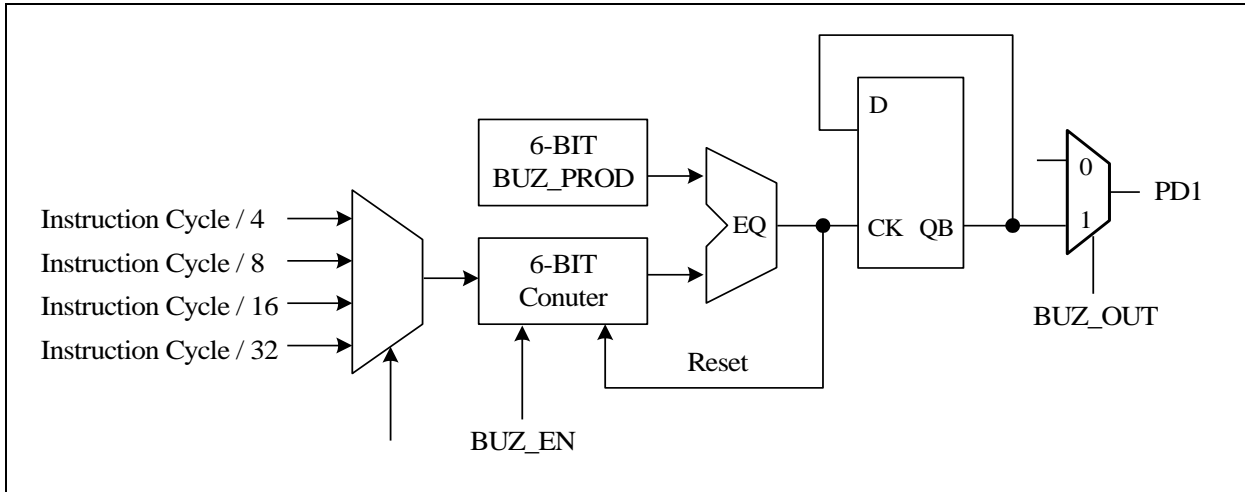
External RC Oscillator



Internal RC Mode

3.7 BUZZER Output

The Buzzer driver consists of 6-bit counter and a clock divider. It generates 50% duty square waveform with wide frequency range. To use the Buzzer function, user needs to set both the Buzzer enable control bit (BUZ_EN) and the Buzzer output pin enable control bit (BUZ_OUT).



BUZ_PROD[5:0] determines output frequency. Frequency calculation is as follows.

$$F_{BZ} = (f_{osc}/2) / (\text{Instruction Cycle Divider}) / (\text{BUZ_PROD} + 1) / 2$$

Output frequency calculation

CPU Clock (fosc) = 8192 KHz

Instruction Cycle = fosc/2 = 8192 KHz/2 = 4096 KHz

Prescaler Ratio (BUZ_PSC) = 2⁵b11 (Instruction Cycle Divider = 32)

Period Data (BUZ_PROD) = 9

$$FBZ = (8192 \text{ KHz}/2) / 32 / (9+1) / 2 = 6.4 \text{ (KHz)}$$

BUZZER example code:

```
movlw      10000000b
movwr      0bh          ; enable BUZZER output to PD1 (BUZ_OUT)

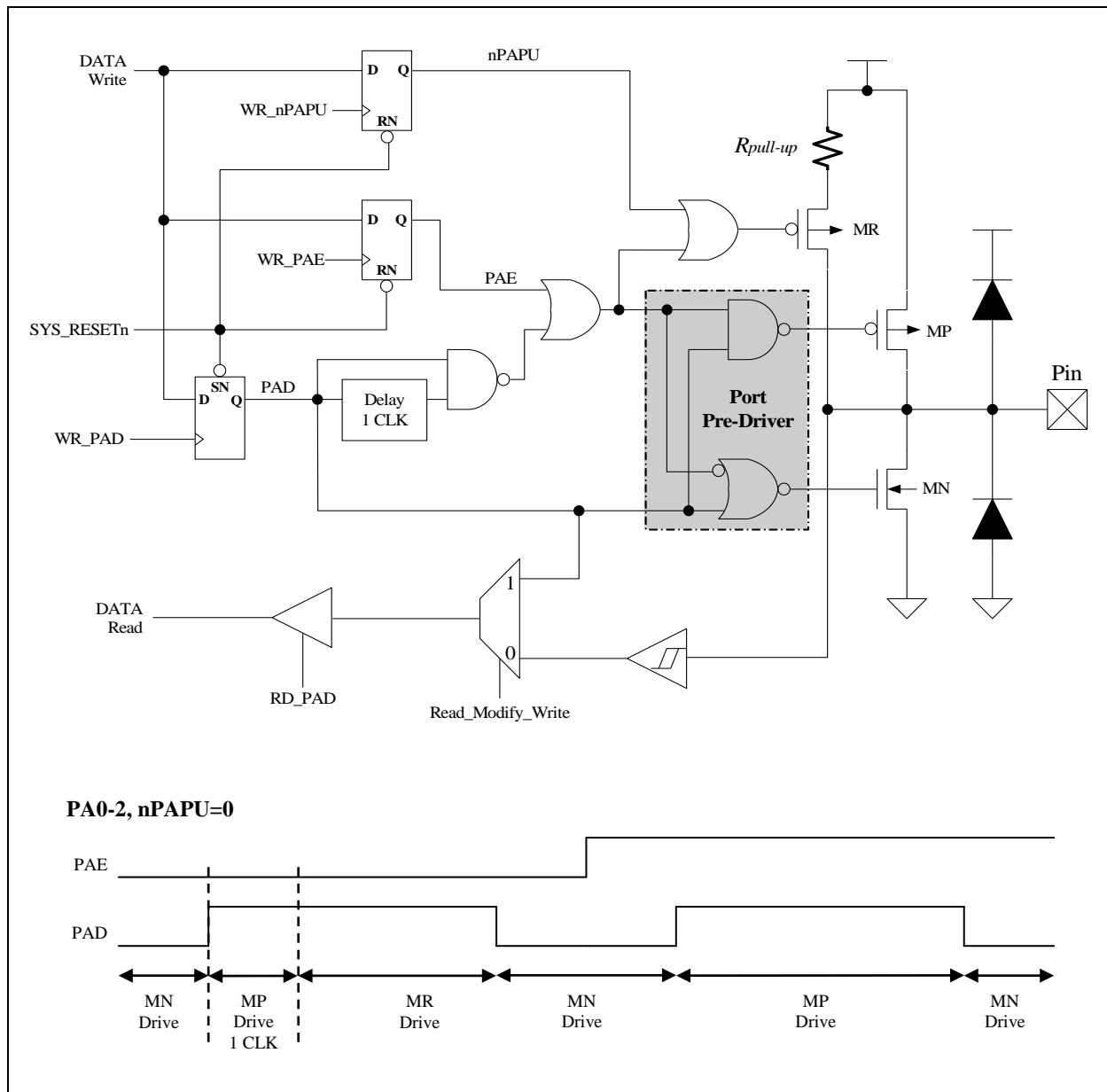
movlw      11001001b   ; (fosc/2)/32 (BUZ_PSC)
movwr      10h         ; Period=9 (BUZ_PROD)

movlw      80h
movwr      0ch         ; enable BUZZER counting (BUZ_EN)
:
:
movlw      00h
movwr      0ch         ; disable BUZZER counting (BUZ_EN)
```

4. I/O Port

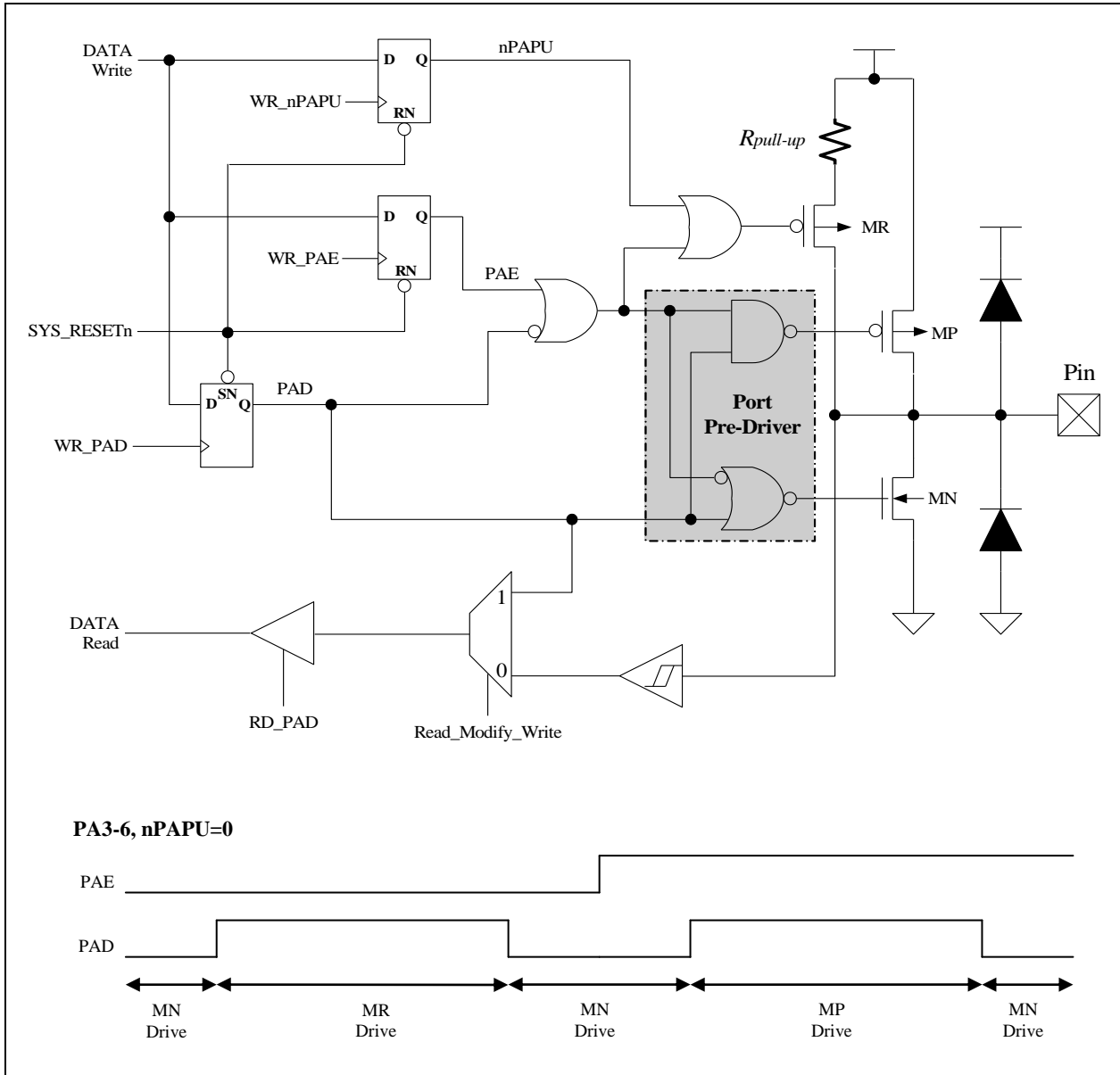
4.1 PA0-2

These pins can be used as Schmitt-trigger input, CMOS push-pull output or “pseudo-open-drain” output. The pull-up resistor is assignable to each pin by S/W setting. To use the pin in Schmitt-trigger input mode, S/W needs to set the PAE=0 and PAD=1. To use the pin in **pseudo-open-drain** mode, S/W sets the PAE=0. The benefit of pseudo-open-drain structure is that the output rise time can be much faster than pure open-drain structure. S/W sets PAE=1 to use the pin in CMOS push-pull output mode. Reading the pin data (PAD) has different meaning. In “Read-Modify-Write” instruction, CPU actually reads the output data register. In the other instructions, CPU reads the pin state. The so-called “Read-Modify-Write” instruction includes BSF, BCF and all instructions using F-Plane as destination.



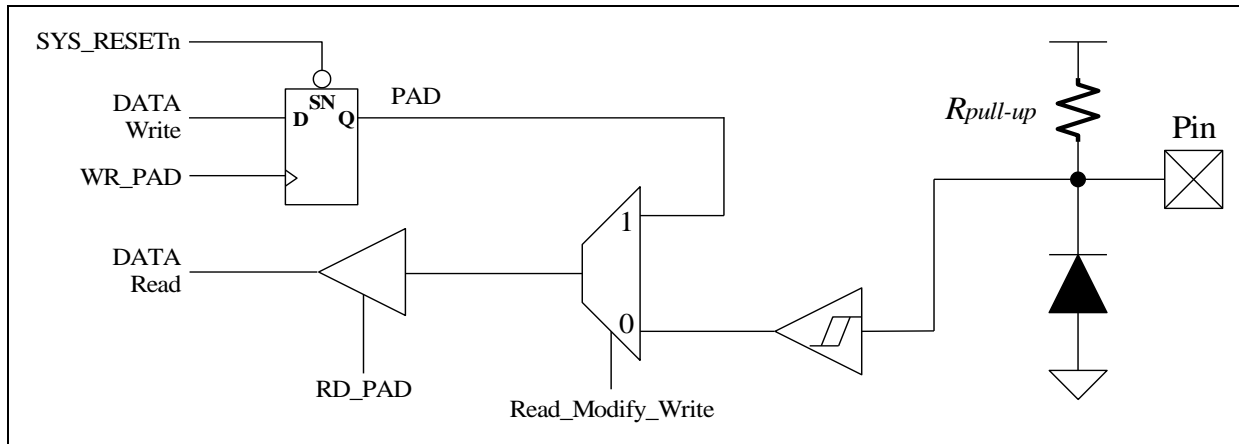
4.2 PA3-6, PB0-1, PD0-7

These pins are almost the same as PA0-2, except they do not support pseudo-open-drain mode. They can be used in pure **open-drain** mode, instead.



4.3 PA7

PA7 can be only used in Schmitt-trigger input mode. The pull-up resistor is always connected to this pin.



MEMORY MAP

F-Plane

Name	Address	R/W	Rst	Description
INDF	00.7~0	R/W	-	Not a physical register, addressing INDF actually point to the register whose address is contained in the FSR register
TIMER0	01.7~0	R/W	0	Timer0 content
PC	02.7~0	R/W	0	Programming Counter [7~0]
RAMBANK	03.5	R/W	0	RAM Bank Selection
TO	03.4	R	0	WDT time out flag, cleared by 'SLEEP', 'CLRWDT' instruction
PD	03.3	R	0	Sleep mode flag, cleared by 'CLRWDT' instruction
ZFLAG	03.2	R/W	0	Zero Flag
DCFLAG	03.1	R/W	0	Decimal Carry Flag
CFLAG	03.0	R/W	0	Carry Flag
FSR	04.7	R	0	Fixed 0
	04.6~0	R/W	-	File Select Register, indirect address mode pointer
PA[7]	05.7	R	-	PA7 pin state
		W	7F	Port A output data register
PAD[6:0]	05.6~0	R	-	Port A pin or "data register" state
		W	3	Port A output data register
PBD[1:0]	06.1~0	R	-	Port B pin or "data register" state
		W	3	Port B output data register
PDD[7:0]	07.7~0	R	-	Port D pin or "data register" state
		W	FF	Port D output data register
TM1I	09.5	R	-	Timer1 interrupt event pending flag, set by H/W while Timer1 overflows
		W	0	write 0: clear this flag; write 1: no action
TM0I	09.4	R	-	Timer0 interrupt event pending flag, set by H/W while Timer0 overflows
		W	0	write 0: clear this flag; write 1: no action
WKT I	09.3	R	-	WKT interrupt event pending flag, set by H/W while WKT time out
		W	0	write 0: clear this flag; write 1: no action
XINT2	09.2	R	-	INT2 pin (PA7) interrupt event pending flag, set by H/W at INT2 pin's falling edge
		W	0	write 0: clear this flag; write 1: no action
XINT1	09.1	R	-	INT1 pin (PA1) interrupt event pending flag, set by H/W at INT1 pin's falling or rising edge
		W	0	write 0: clear this flag; write 1: no action
XINT0	09.0	R	-	INT0 pin (PA6) interrupt event pending flag, set by H/W at INT0 pin's falling edge
		W	0	write 0: clear this flag; write 1: no action
TIMER1	0a.7~0	R/W	0	Timer1 content
PWM0DUTY	0c.7~0	R/W	0	PWM0 duty 8-bit MSB
	0d.7~6	R/W	0	PWM0 duty 2-bit LSB
PWM1DUTY	0e.7~0	R/W	0	PWM1 duty 8-bit MSB
	0f.7~6	R/W	0	PWM1 duty 2-bit LSB
ADCQ	10.7~0	R	-	ADC conversion result ADCQ[11:4]
	11.7~4	R	-	ADC conversion result ADCQ[3:0]
ADCSTART	11.3	R	-	H/W clears this bit after ADC end of conversion
		W	0	S/W sets this bit to start ADC conversion
ADCSEL	11.2~0	R/W	0	ADC channel select; 0: ADC0, 1: ADC1, ..., 7: ADC7
RAM	20~27	R/W	-	Internal RAM – Common Area
	28~7F	R/W	-	Internal RAM – RAM Bank0
	28~7F	R/W	-	Internal RAM – RAM Bank1

R-Plane

Name	Address	R/W	Rst	Discription
TCOUT_PSC	02.7~6	W	0	TCOUT Pre-Scale 00: TCOUT output clock is "Instruction Cycle" divided by 1 01: TCOUT output clock is "Instruction Cycle" divided by 2 10: TCOUT output clock is "Instruction Cycle" divided by 4 11: TCOUT output clock is "Instruction Cycle" divided by 8
T0IEDGE	02.5	W	0	0: T0I (PA2) rising edge to increase Timer0/PSC count 1: T0I (PA2) falling edge to increase Timer0/PSC count
SELT0I	02.4	W	0	0: Timer0/PSC clock source is "Instruction Cycle" 1: Timer0/PSC clock source is T0I pin
TM0PSC	02.3~0	W	0	Timer0 Pre-Scale 0000: Timer0 input clock is "Instruction Cycle" divided by 1 0001: Timer0 input clock is "Instruction Cycle" divided by 2 ~ 0111: Timer0 input clock is "Instruction Cycle" divided by 128 1000: Timer0 input clock is "Instruction Cycle" divided by 256
PWRDOWN	03	W		write this register to enter Power-Down Mode
CLRWDT	04	W		write this register to clear WDT/WKT
PAE	05.6~3	W	0	Each bit controls its corresponding pin, if the bit is 0: the pin is open-drain output or Schmitt-trigger input 1: the pin is CMOS push-pull output
	05.2~0	W	0	Each bit controls its corresponding pin, if the bit is 0: the pin is pseudo-open-drain output or Schmitt-trigger input 1: the pin is CMOS push-pull output
PBE	06.1~0	W	0	Each bit controls its corresponding pin, if the bit is 0: the pin is open-drain output or Schmitt-trigger input 1: the pin is CMOS push-pull output
PDE	07.7~0	W	0	Each bit controls its corresponding pin, if the bit is 0: the pin is open-drain output or Schmitt-trigger input 1: the pin is CMOS push-pull output
nPAPU	08.6~0	W	7F	Each bit controls its corresponding pin, if the bit is 0: the pin pull up resistor is enabled, except a. the pin's output data register (PAD) is 0 b. the pin's CMOS push-pull mode is chosen (PAE=1) c. the pin is working for Crystal or external RC oscillation d. PA0 is working for PWM0 output 1: the pin pull up resistor is disabled
nPBPU	09.1~0	W	3	Each bit controls its corresponding pin, if the bit is 0: the pin pull up resistor is enabled, except a. the pin's output data register (PBD) is 0 b. the pin's CMOS push-pull mode is chosen (PBE=1) c. PB0 is working for PWM1 output 1: the pin pull up resistor is disabled
nPDPU	0a.7~0	W	FF	Each bit controls its corresponding pin, if the bit is 0: the pin pull up resistor is enabled, except a. the pin's output data register (PDD) is 0 b. the pin's CMOS push-pull mode is chosen (PDE=1) c. the pin is working for T1OUT/BUZZER/TCOUT output 1: the pin pull up resistor is disabled

Name	Address	R/W	Rst	Discription
BUZ_OUT	0b.7	W	0	0: disable BUZZER output to PD1 pin 1: enable BUZZER output to PD1 pin
PWM0_OUT	0b.6	W	0	0: disable PWM0 output to PA0 pin 1: enable PWM0 output to PA0 pin
PWM1_OUT	0b.5	W	0	0: disable PWM1 output to PB0 pin 1: enable PWM1 output to PB0 pin
INT1EDGE	0b.4	W	0	0: INT1 pin (PA1) falling edge to trigger interrupt event 1: INT1 pin (PA1) rising edge to trigger interrupt event
TC_OUT	0b.3	W	0	0: disable Instruction Clock divider output to PD6 pin 1: enable Instruction Clock divider output to PD6 pin
TM1_OUT	0b.2	W	0	0: disable Timer1 match out (T1OUT) to PD0 1: enable Timer1 match out (T1OUT) to PD0
WKTpsc	0b.1~0	W	11	WDT/WKT period (VCC=5V) 00: 11 ms 01: 23 ms 10: 45 ms 11: 90 ms
BUZ_EN	0c.7	W	0	0: disable BUZZER timer counting 1: enable BUZZER timer counting
ADCLKS	0c.6~4	W	0	000: ADC clock is "Instruction Cycle" divided by 128 001: ADC clock is "Instruction Cycle" divided by 64 ~ 111: ADC clock is "Instruction Cycle" divided by 1
TM1PSC	0c.3~0	W	0	0000: Timer1 input clock is "Instruction Cycle" divided by 1 0001: Timer1 input clock is "Instruction Cycle" divided by 2 ~ 0111: Timer1 input clock is "Instruction Cycle" divided by 128 1000: Timer1 input clock is "Instruction Cycle" divided by 256
TM1RELD	0d.7~0	W	0	Timer1 reload offset value while it rolls over
TM1IE	0e.5	W	0	Timer1 interrupt enable, 1=enable, 0=disable
TM0IE	0e.4	W	0	Timer0 interrupt enable, 1=enable, 0=disable
WKTIE	0e.3	W	0	Wakeup Timer interrupt enable, 1=enable, 0=disable
XINT2E	0e.2	W	0	INT2 pin (PA7) interrupt enable, 1=enable, 0=disable
XINT1E	0e.1	W	0	INT1 pin (PA1) interrupt enable, 1=enable, 0=disable
XINT0E	0e.0	W	0	INT0 pin (PA6) interrupt enable, 1=enable, 0=disable
TESTREG	0f.1~0	W	0	Test mode register, for manufacturer only, user does not write it
BUZ_PSC	10.7~6	W	0	BUZZER Clock Prescaler 00: BUZZER clock is "Instruction Cycle" divided by 4 01: BUZZER clock is "Instruction Cycle" divided by 8 10: BUZZER clock is "Instruction Cycle" divided by 16 11: BUZZER clock is "Instruction Cycle" divided by 32
BUZ_PROD	10.5~0	W	0	BUZZER Period Data. BUZZER output is BUZZER Clock divided by BUZ_PROD
IVC_REG	11.4~3	W	0	Built-in regulator control in sleep mode 00: VCC > 4.5 V 01: 4.5 V > VCC > 3.6 V 10: 3.6 V > VCC
ADC_TRIM	11.2~0	W	0	Test mode register, for manufacturer only, user does not write it
nADC_IE	12.7~0	W	ff	Each bit controls its corresponding ADC7~0 enable pin, if the bit is 0: the corresponding pin is ADC input 1: the corresponding pin is digital input

INSTRUCTION SET

Each instruction is a 14-bit word divided into an OPCODE, which specifies the instruction type, and one or more operands, which further specify the operation of the instruction. The instructions can be categorized as byte-oriented, bit-oriented and literal operations list in the following table.

For byte-oriented instructions, “f” or “r” represents the address designator and “d” represents the destination designator. The address designator is used to specify which address in Program memory is to be used by the instruction. The destination designator specifies where the result of the operation is to be placed. If “d” is “0”, the result is placed in the W register. If “d” is “1”, the result is placed in the address specified in the instruction.

For bit-oriented instructions, “b” represents a bit field designator, which selects the number of the bit affected by the operation, while “f” represents the address designator. For literal operations, “k” represents the literal or constant value.

Field / Legend	Description
f	F-Plane Register File Address
r	R-Plane Register File Address
b	Bit address
k	Literal. Constant data or label
d	Destination selection field, 0: Working register, 1: Register file
W	Working Register
Z	Zero Flag
C	Carry Flag
DC	Decimal Carry Flag
PC	Program Counter
TOS	Top Of Stack
GIE	Global Interrupt Enable Flag (i-Flag)
[]	Option Field
()	Contents
.	Bit Field
B	Before
A	After
←	Assign direction

Mnemonic		Op Code	Cycle	Flag Affect	Description
Byte-Oriented File Register Instruction					
ADDWF	f,d	00 0111 dfff ffff	1	C, DC, Z	Add W and "f"
ANDWF	f,d	00 0101 dfff ffff	1	Z	AND W with "f"
CLRF	f	00 0001 1fff ffff	1	Z	Clear "f"
CLRWF		00 0001 0100 0000	1	Z	Clear W
COMF	f,d	00 1001 dfff ffff	1	Z	Complement "f"
DECF	f,d	00 0011 dfff ffff	1	Z	Decrement "f"
DECFSZ	f,d	00 1011 dfff ffff	1 or 2	-	Decrement "f", skip if zero
INCF	f,d	00 1010 dfff ffff	1	Z	Increment "f"
INCFSZ	f,d	00 1111 dfff ffff	1 or 2	-	Increment "f", skip if zero
IORWF	f,d	00 0100 dfff ffff	1	Z	OR W with "f"
MOVWF	f	00 1000 0fff ffff	1	-	Move "f" to W
MOVWF	f	00 0000 1fff ffff	1	-	Move W to "f"
MOVWR	r	00 0000 00rr rrrr	1	-	Move W to "r"
RLF	f,d	00 1101 dfff ffff	1	C	Rotate left "f" through carry
RRF	f,d	00 1100 dfff ffff	1	C	Rotate right "f" through carry
SUBWF	f,d	00 0010 dfff ffff	1	C, DC, Z	Subtract W from "f"
SWAPF	f,d	00 1110 dfff ffff	1	-	Swap nibbles in "f"
TESTZ	f	00 1000 1fff ffff	1	Z	Test if "f" is zero
XORWF	f,d	00 0110 dfff ffff	1	Z	XOR W with "f"
Bit-Oriented File Register Instruction					
BCF	f,b	01 000b bbff ffff	1	-	Clear "b" bit of "f"
BSF	f,b	01 001b bbff ffff	1	-	Set "b" bit of "f"
BTFSC	f,b	01 010b bbff ffff	1 or 2	-	Test "b" bit of "f", skip if clear
BTFSS	f,b	01 011b bbff ffff	1 or 2	-	Test "b" bit of "f", skip if set
Literal and Control Instruction					
ADDLW	k	01 1100 kkkk kkkk	1	C, DC, Z	Add Literal "k" and W
ANDLW	k	01 1011 kkkk kkkk	1	Z	AND Literal "k" with W
CALL	k	10 kkkk kkkk kkkk	2	-	Call subroutine "k"
CLRWDTC		00 0000 0000 0100	1	TO, PD	Clear Watchdog/Wakeup Timer
GOTO	k	11 kkkk kkkk kkkk	2	-	Jump to branch "k"
IORLW	k	01 1010 kkkk kkkk	1	Z	OR Literal "k" with W
MOVLW	k	01 1001 kkkk kkkk	1	-	Move Literal "k" to W
NOP		00 0000 0000 0000	1	-	No operation
RET		00 0000 0100 0000	2	-	Return from subroutine
RETI		00 0000 0110 0000	2	-	Return from interrupt
RETLW	k	01 1000 kkkk kkkk	2	-	Return with Literal in W
SLEEP		00 0000 0000 0011	1	TO, PD	Go into standby mode, Clock oscillation stops
XORLW	k	01 1111 kkkk kkkk	1	Z	XOR Literal "k" with W

ADDLW

Add Literal “k” and W

Syntax	ADDLW k	
Operands	k : 00h ~ FFh	
Operation	$(W) \leftarrow (W) + k$	
Status Affected	C, DC, Z	
OP-Code	01 1100 kkkk kkkk	
Description	The contents of the W register are added to the eight-bit literal ‘k’ and the result is placed in the W register.	
Cycle	1	
Example	ADDLW 0x15	B : W = 0x10 A : W = 0x25

ADDWF

Add W and “f”

Syntax	ADDWF f [,d]	
Operands	f : 00h ~ 7Fh d : 0, 1	
Operation	$(\text{Destination}) \leftarrow (W) + (f)$	
Status Affected	C, DC, Z	
OP-Code	00 0111 dfff ffff	
Description	Add the contents of the W register with register ‘f’. If ‘d’ is 0, the result is stored in the W register. If ‘d’ is 1, the result is stored back in register ‘f’.	
Cycle	1	
Example	ADDWF FSR, 0	B : W = 0x17, FSR = 0xC2 A : W = 0xD9, FSR = 0xC2

ANDLW

Logical AND Literal "k" with W

Syntax	ANDLW k	
Operands	k : 00h ~ FFh	
Operation	$(W) \leftarrow (W) \text{ ‘AND’ } (f)$	
Status Affected	Z	
OP-Code	01 1011 kkkk kkkk	
Description	The contents of W register are AND’ed with the eight-bit literal ‘k’. The result is placed in the W register.	
Cycle	1	
Example	ANDLW 0x5F	B : W = 0xA3 A : W = 0x03

ANDWF

AND W with “f”

Syntax	ANDWF f [,d]	
Operands	f : 00h ~ 7Fh d : 0, 1	
Operation	$(\text{Destination}) \leftarrow (W) \text{ ‘AND’ } (f)$	
Status Affected	Z	
OP-Code	00 0101 dfff ffff	
Description	AND the W register with register ‘f’. If ‘d’ is 0, the result is stored in the W register. If ‘d’ is 1, the result is stored back in register ‘f’.	
Cycle	1	
Example	ANDWF FSR, 1	B : W = 0x17, FSR = 0xC2 A : W = 0x17, FSR = 0x02

BCF Clear "b" bit of "f"

Syntax	BCF f [,b]	
Operands	f : 00h ~ 3Fh b : 0 ~ 7	
Operation	(f.b) ← 0	
Status Affected	-	
OP-Code	01 000b bbff ffff	
Description	Bit 'b' in register 'f' is cleared.	
Cycle	1	
Example	BCF FLAG_REG, 7	B : FLAG_REG = 0xC7 A : FLAG_REG = 0x47

BSF Set "b" bit of "f"

Syntax	BSF f [,b]	
Operands	f : 00h ~ 3Fh b : 0 ~ 7	
Operation	(f.b) ← 1	
Status Affected	-	
OP-Code	01 001b bbff ffff	
Description	Bit 'b' in register 'f' is set.	
Cycle	1	
Example	BSF FLAG_REG, 7	B : FLAG_REG = 0x0A A : FLAG_REG = 0x8A

BTFSC Test "b" bit of "f", skip if clear(0)

Syntax	BTFSC f [,b]	
Operands	f : 00h ~ 3Fh b : 0 ~ 7	
Operation	Skip next instruction if (f.b) = 0	
Status Affected	-	
OP-Code	01 010b bbff ffff	
Description	If bit 'b' in register 'f' is '1', then the next instruction is executed. If bit 'b' in register 'f' is '0', then the next instruction is discarded, and a NOP is executed instead, making this a 2nd cycle instruction.	
Cycle	1 or 2	
Example	LABEL1 BTFSC FLAG, 1 TRUE GOTO SUB1 FALSE ...	B : PC = LABEL1 A : if FLAG.1 = 0, PC = FALSE if FLAG.1 = 1, PC = TRUE

BTFSS Test "b" bit of "f", skip if set(1)

Syntax	BTFSS f [,b]	
Operands	f : 00h ~ 3Fh b : 0 ~ 7	
Operation	Skip next instruction if (f.b) = 1	
Status Affected	-	
OP-Code	01 011b bbff ffff	
Description	If bit 'b' in register 'f' is '0', then the next instruction is executed. If bit 'b' in register 'f' is '1', then the next instruction is discarded, and a NOP is executed instead, making this a 2nd cycle instruction.	
Cycle	1 or 2	
Example	LABEL1 BTFSS FLAG, 1 TRUE GOTO SUB1 FALSE ...	B : PC = LABEL1 A : if FLAG.1 = 0, PC = TRUE if FLAG.1 = 1, PC = FALSE

CALL Call subroutine "k"

Syntax	CALL k
Operands	K : 00h ~ FFFh
Operation	Operation: TOS ← (PC)+ 1, PC.11~0 ← k
Status Affected	-
OP-Code	10 kkkkk kkkk kkkk
Description	Call Subroutine. First, return address (PC+1) is pushed onto the stack. The 12-bit immediate address is loaded into PC bits <11:0>. CALL is a two-cycle instruction.
Cycle	2
Example	LABEL1 CALL SUB1 B : PC = LABEL1 A : PC = SUB1, TOS = LABEL1+1

CLRF Clear "f"

Syntax	CLRF f
Operands	f : 00h ~ 7Fh
Operation	(f) ← 00h, Z ← 1
Status Affected	Z
OP-Code	00 0001 1fff ffff
Description	The contents of register 'f' are cleared and the Z bit is set.
Cycle	1
Example	CLRF FLAG_REG B : FLAG_REG = 0x5A A : FLAG_REG = 0x00, Z = 1

CLRW Clear W

Syntax	CLRW
Operands	-
Operation	(W) ← 00h, Z ← 1
Status Affected	Z
OP-Code	00 0001 0100 0000
Description	W register is cleared and Zero bit (Z) is set.
Cycle	1
Example	CLRW B : W = 0x5A A : W = 0x00, Z = 1

CLRWDT Clear Watchdog Timer

Syntax	CLRWDT
Operands	-
Operation	WDT/WKT Timer ← 00h
Status Affected	TO, PD
OP-Code	00 0000 0000 0100
Description	CLRWDT instruction clears the Watchdog/Wakeup Timer
Cycle	1
Example	CLRWDT B : WDT counter = ? A : WDT counter = 0x00

COMF	Complement “f”	
Syntax	COMF f [,d]	
Operands	f : 00h ~ 7Fh, d : 0, 1	
Operation	(destination) ← (\bar{f})	
Status Affected	Z	
OP-Code	00 1001 dfff ffff	
Description	The contents of register ‘f’ are complemented. If ‘d’ is 0, the result is stored in W. If ‘d’ is 1, the result is stored back in register ‘f’.	
Cycle	1	
Example	COMF REG1,0	B : REG1 = 0x13 A : REG1 = 0x13, W = 0xEC

DECF	Decrement “f”	
Syntax	DECF f [,d]	
Operands	f : 00h ~ 7Fh, d : 0, 1	
Operation	(destination) ← (f) - 1	
Status Affected	Z	
OP-Code	00 0011 dfff ffff	
Description	Decrement register ‘f’. If ‘d’ is 0, the result is stored in the W register. If ‘d’ is 1, the result is stored back in register ‘f’.	
Cycle	1	
Example	DECF CNT, 1	B : CNT = 0x01, Z = 0 A : CNT = 0x00, Z = 1

DECFSZ	Decrement “f”, Skip if 0	
Syntax	DECFSZ f [,d]	
Operands	f : 00h ~ 7Fh, d : 0, 1	
Operation	(destination) ← (f) - 1, skip next instruction if result is 0	
Status Affected	-	
OP-Code	00 1011 dfff ffff	
Description	The contents of register ‘f’ are decremented. If ‘d’ is 0, the result is placed in the W register. If ‘d’ is 1, the result is placed back in register ‘f’. If the result is 1, the next instruction is executed. If the result is 0, then a NOP is executed instead, making it a 2 cycle instruction.	
Cycle	1 or 2	
Example	LABEL1 DECFSZ CNT, 1 GOTO LOOP CONTINUE	B : PC = LABEL1 A : CNT = CNT - 1 if CNT=0, PC = CONTINUE if CNT≠0, PC = LABEL1+1

GOTO
Unconditional Branch

Syntax	GOTO k	
Operands	k : 00h ~ FFFh	
Operation	PC.11~0 ← k	
Status Affected	-	
OP-Code	11 kkkk kkkk kkkk	
Description	GOTO is an unconditional branch. The 12-bit immediate value is loaded into PC bits <11:0>. GOTO is a two-cycle instruction.	
Cycle	2	
Example	LABEL1 GOTO SUB1	B : PC = LABEL1 A : PC = SUB1

INCF
Increment "f"

Syntax	INCF f [,d]	
Operands	f : 00h ~ 7Fh	
Operation	(destination) ← (f) + 1	
Status Affected	Z	
OP-Code	00 1010 dfff ffff	
Description	The contents of register 'f' are incremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.	
Cycle	1	
Example	INCF CNT, 1	B : CNT = 0xFF, Z = 0 A : CNT = 0x00, Z = 1

INCFSZ
Increment "f", Skip if 0

Syntax	INCFSZ f [,d]	
Operands	f : 00h ~ 7Fh, d : 0, 1	
Operation	(destination) ← (f) + 1, skip next instruction if result is 0	
Status Affected	-	
OP-Code	00 1111 dfff ffff	
Description	The contents of register 'f' are incremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'. If the result is 1, the next instruction is executed. If the result is 0, a NOP is executed instead, making it a 2 cycle instruction.	
Cycle	1 or 2	
Example	LABEL1 INCFSZ CNT, 1 GOTO LOOP CONTINUE	B : PC = LABEL1 A : CNT = CNT + 1 if CNT=0, PC = CONTINUE if CNT≠0, PC = LABEL1+1

IORLW
Inclusive OR Literal with W

Syntax	IORLW k	
Operands	k : 00h ~ FFh	
Operation	(W) ← (W) OR k	
Status Affected	Z	
OP-Code	01 1010 kkkk kkkk	
Description	The contents of the W register are OR'ed with the eight-bit literal 'k'. The result is placed in the W register.	
Cycle	1	
Example	IORLW 0x35	B : W = 0x9A A : W = 0xBF, Z = 0

IORWF Inclusive OR W with “f”

Syntax	IORWF f [,d]	
Operands	f : 00h ~ 7Fh, d : 0, 1	
Operation	(destination) ← (W) OR k	
Status Affected	Z	
OP-Code	00 0100 dfff ffff	
Description	Inclusive OR the W register with register ‘f’. If ‘d’ is 0, the result is placed in the W register. If ‘d’ is 1, the result is placed back in register ‘f’.	
Cycle	1	
Example	IORWF RESULT, 0	B : RESULT = 0x13, W = 0x91 A : RESULT = 0x13, W = 0x93, Z = 0

MOVFW Move “f” to W

Syntax	MOVFW f	
Operands	f : 00h ~ 7Fh	
Operation	(W) ← (f)	
Status Affected	-	
OP-Code	00 1000 0fff ffff	
Description	The contents of register f are moved to W register.	
Cycle	1	
Example	MOV FSR, 0	B : W = ? A : W ← f, if W = 0 Z = 1

MOVLW Move Literal to W

Syntax	MOVLW k	
Operands	k : 00h ~ FFh	
Operation	(W) ← k	
Status Affected	-	
OP-Code	01 1001 kkkk kkkk	
Description	The eight-bit literal ‘k’ is loaded into W register. The don’t cares will assemble as 0’s.	
Cycle	1	
Example	MOVLW 0x5A	B : W = ? A : W = 0x5A

MOVWF Move W to “f”

Syntax	MOVWF f	
Operands	f : 00h ~ 7Fh	
Operation	(f) ← (W)	
Status Affected	-	
OP-Code	00 0000 1fff ffff	
Description	Move data from W register to register ‘f’.	
Cycle	1	
Example	MOVWF REG1	B : REG1 = 0xFF, W = 0x4F A : REG1 = 0x4F, W = 0x4F

XORLW Exclusive OR Literal with W

Syntax	XORLW k	
Operands	k : 00h ~ FFh	
Operation	(W) ← (W) XOR k	
Status Affected	Z	
OP-Code	01 1111 kkkk kkkk	
Description	The contents of the W register are XOR'ed with the eight-bit literal 'k'. The result is placed in the W register.	
Cycle	1	
Example	XORLW 0xAF	B : W = 0xB5 A : W = 0x1A

XORWF Exclusive OR W with "f"

Syntax	XORWF f [,d]	
Operands	f : 00h ~ 7Fh, d : 0, 1	
Operation	(destination) ← (W) XOR (f)	
Status Affected	Z	
OP-Code	00 0110 dfff ffff	
Description	Exclusive OR the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.	
Cycle	1	
Example	XORWF REG 1	B : REG = 0xAF, W = 0xB5 A : REG = 0x1A, W = 0xB5

ELECTRICAL CHARACTERISTICS

1. Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$)

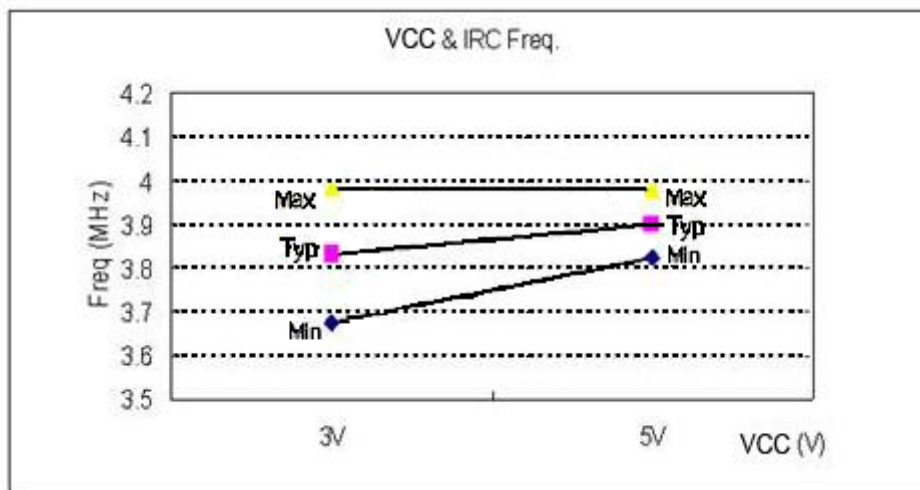
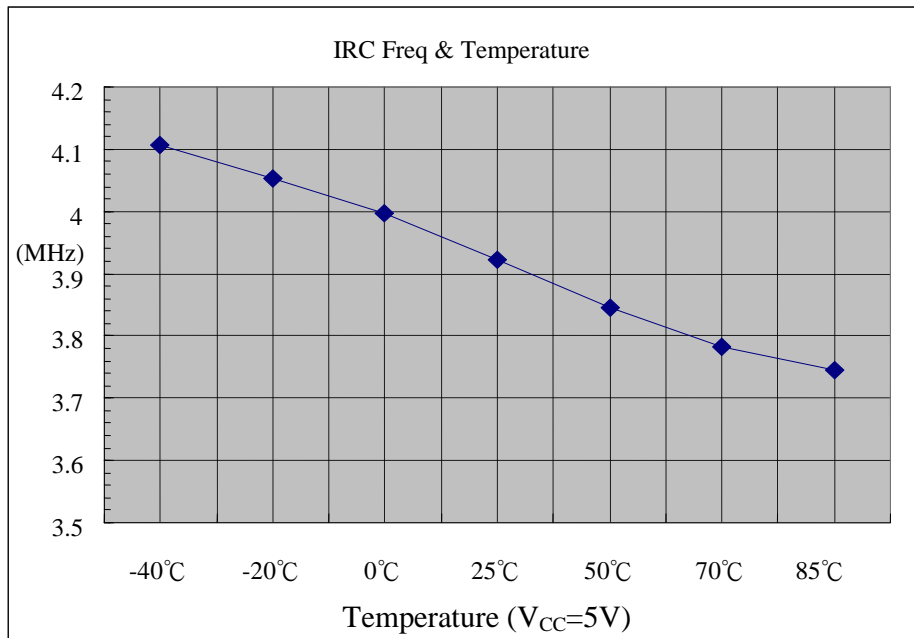
Parameter	Rating	Unit
Supply voltage	$V_{SS} - 0.3$ to $V_{SS} + 6.5$	V
Input voltage	$V_{SS} - 0.3$ to $V_{CC} + 0.3$	
Output voltage	$V_{SS} - 0.3$ to $V_{CC} + 0.3$	
Output current high per 1 PIN	-25	mA
Output current high per all PIN	-80	
Output current low per 1 PIN	+30	
Output current low per all PIN	+150	
Maximum Operating Voltage	5.5	V
Operating temperature	-40 to +85	$^\circ\text{C}$
Storage temperature	-65 to +150	

2. DC Characteristics ($T_A = 25\text{ C}$, $V_{CC} = 2.0\text{V}$ to 5.5V)

Parameter	Sym	Conditions		Min	Typ	Max	Unit		
Input High Voltage	V_{IH}	All Input, except PA7	$V_{CC} = 5\text{V}$	$0.5V_{CC}$			V		
			$V_{CC} = 3\text{V}$	$0.55V_{CC}$			V		
		PA7	$V_{CC} = 3\sim 5\text{V}$	$0.6V_{CC}$			V		
Input Low Voltage	V_{IL}	All Input, except PA7	$V_{CC} = 5\text{V}$			$0.3V_{CC}$	V		
			$V_{CC} = 3\text{V}$			$0.25V_{CC}$	V		
		PA7	$V_{CC} = 3\sim 5\text{V}$			$0.4V_{CC}$	V		
Output High Current	I_{OH}	All Output	$V_{CC} = 5\text{V}, V_{OH} = 4.5\text{V}$	3	7		mA		
			$V_{CC} = 3\text{V}, V_{OH} = 2.7\text{V}$	2	4				
Output Low Current	I_{OL}	All Output	$V_{CC} = 5\text{V}, V_{OL} = 0.5\text{V}$	9	18		mA		
			$V_{CC} = 3\text{V}, V_{OL} = 0.3\text{V}$	4	8				
Input Leakage Current (pin high)	I_{ILH}	All Input	$V_{IN} = V_{CC}$	–	–	1	uA		
Input Leakage Current (pin low)	I_{ILL}	All Input	$V_{IN} = 0\text{V}$	–	–	–1	uA		
Power Supply Current	I_{CC}	Run 10 MHz No Load	$V_{CC} = 4.5$ to 5.5V	–	5		mA		
			$V_{CC} = 2.0\text{V}$		1				
		Stop mode No Load (TM57FA40A)	$V_{CC} = 5\text{V}, \text{IVC_REG} = 0, \text{IVC}$ disable	–	5	7	uA		
			$V_{CC} = 5\text{V}, \text{IVC}$ enable			200			
			$V_{CC} = 2.6\text{V}, \text{IVC_REG} = 2, \text{IVC}$ disable		5	7			
		Stop mode No Load (TM57FA40)	$V_{CC} = 5\text{V}, \text{IVC_REG} = 0, \text{IVC}$ disable	–	0.1	1	uA		
			$V_{CC} = 5\text{V}, \text{IVC}$ enable			200			
			$V_{CC} = 2.6\text{V}, \text{IVC_REG} = 2, \text{IVC}$ disable		0.1	1			
		System Clock Frequency	f_{OSC}	$V_{CC} > LVR_{th}$	$V_{CC} = 3.0\text{V}$	–		12	MHz
					$V_{CC} = 2.6\text{V}$			10	
$V_{CC} = 2.4\text{V}$	4~8								
LVR reference Voltage		V_{LVR}	1.8	2.1	2.3	V			
			2.6	2.9	3.2				
LVR Hysteresis Voltage		V_{HYST}	–	± 0.1	–	V			
Low Voltage Detection time		t_{LVR}	100	–	–	μs			
Pull-Up Resistor	R_p	$V_{IN} = 0\text{V}$ Ports A/B/D	$V_{CC} = 5\text{V}$		130		k		
			$V_{CC} = 3\text{V}$		300				
		$V_{IN} = 0\text{V}$ PA7	$V_{CC} = 5\text{V}$		80		k		
			$V_{CC} = 3\text{V}$		90				

3. Clock Timing ($T_A = -40\text{ C to }+85\text{ C}$)

Parameter	Condition		Min	Typ	Max	Unit
External RC Frequency	$V_{CC} = 3V$	R = 5K C = 33 pF	–	1.8	–	MHz
		R = 10K C = 100 pF	–	0.73	–	
		R = 100K C = 300 pF	–	0.04	–	
	$V_{CC} = 5V$	R = 5K C = 33 pF	–	2.5	–	
		R = 10K C = 100 pF	–	0.66	–	
		R = 100K C = 300 pF	–	0.03	–	
Internal RC Frequency	$V_{CC} = 4.75\text{ to }5.25V$		Typ-2%	3.9	Typ+2%	MHz
	$V_{CC} = 2.8\text{ to }3.2V$		Typ+4%	3.83	Typ+4%	



4. Reset Timing Characteristics ($T_A = 25^\circ\text{C}$, $V_{CC} = 2.0\text{V}$ to 5.5V)

Parameter	Conditions	Min	Typ	Max	Unit
RESET Input Low width	Input $V_{CC} = 5\text{V} \pm 10\%$	3	–	–	μs
WDT wakeup time	$V_{CC} = 5\text{V}$, WKTPSC = 11	80	90	100	ms
	$V_{CC} = 3\text{V}$, WKTPSC = 11	108	120	132	
CPU start up time	$V_{CC} = 5\text{V}$	–	3.5	–	ms

5. ADC Electrical Characteristics ($T_A = 25^\circ\text{C}$, $V_{CC} = 2.0\text{V}$ to 5.5V , $V_{SS} = 0\text{V}$)

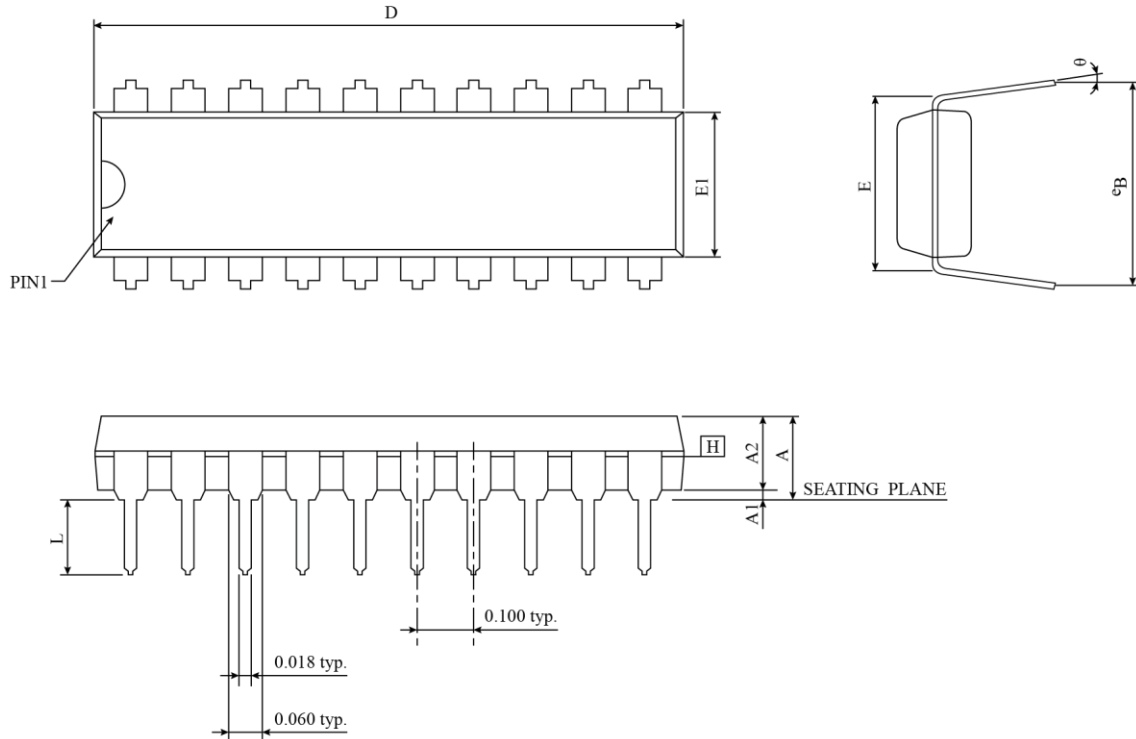
Parameter	Conditions	Min	Typ	Max	Units
Total Accuracy	$V_{CC} = 5.12\text{V}$, $V_{SS} = 0\text{V}$	–	± 2.5	± 4	LSB
Integral Non-Linearity		–	± 3.2	± 5	
Max Input Clock (f_{ADC})	–	–	–	2	MHz
Conversion Time	$f_{\text{ADC}} = 2\text{MHz}$	–	25	–	μs
Input Voltage	–	VSS	–	V_{CC}	V

PACKAGING INFORMATION

The ordering information:

Ordering number	Package
TM57FA40-MTP TM57FA40A-MTP	Wafer / Dice blank chip
TM57FA40-COD TM57FA40A-COD	Wafer / Dice with code
TM57FA40-MTP-03 TM57FA40A-MTP-03	DIP 16-pin (300 mil)
TM57FA40-MTP-16 TM57FA40A-MTP-16	SOP 16-pin (150 mil)
TM57FA40-MTP-05 TM57FA40A-MTP-05	DIP 20-pin (300 mil)
TM57FA40-MTP-21 TM57FA40A-MTP-21	SOP 20-pin (300 mil)
TM57FA40-MTP-01 TM57FA40A-MTP-01	DIP 8-pin (300 mil)
TM57FA40-MTP-14 TM57FA40A-MTP-14	SOP 8-pin (150 mil)

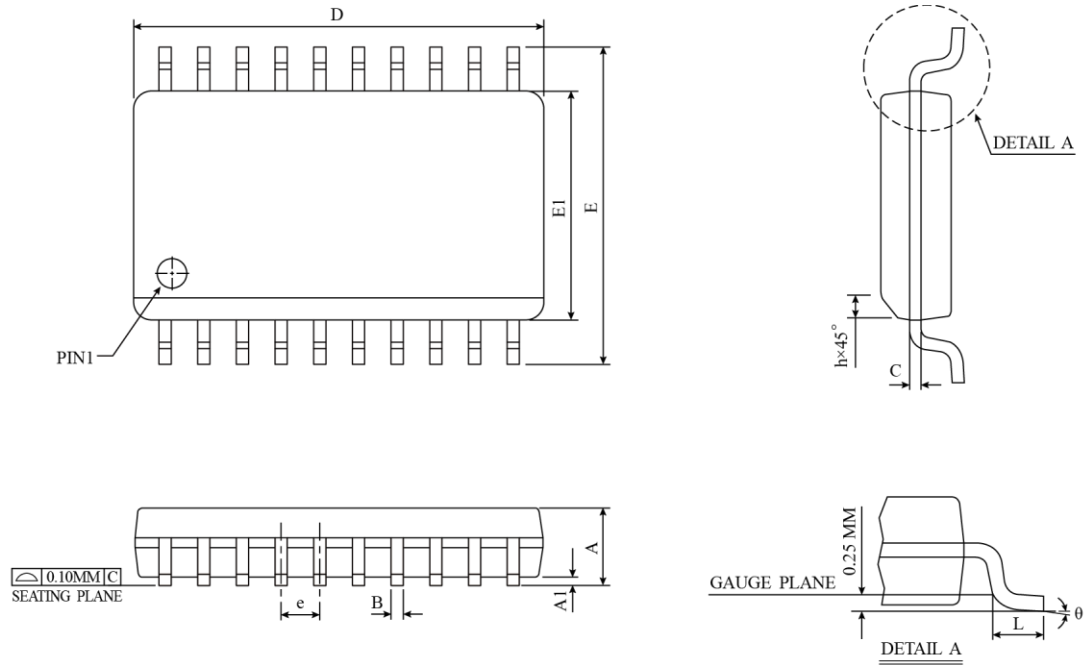
20-DIP Package Dimension



SYMBOL	DIMENSION IN MM		DIMENSION IN INCH	
	MIN	MAX	MIN	MAX
A	-	4.445	-	0.175
A1	0.381	-	0.015	-
A2	3.175	3.429	0.125	0.135
D	25.705	26.416	1.012	1.040
E	7.620	7.874	0.300	0.310
E1	6.223	6.477	0.245	0.255
L	3.048	3.556	0.120	0.140
eB	8.509	9.525	0.335	0.375
θ	0°	15°	0°	15°
JEDEC	MS-001 (AD)			

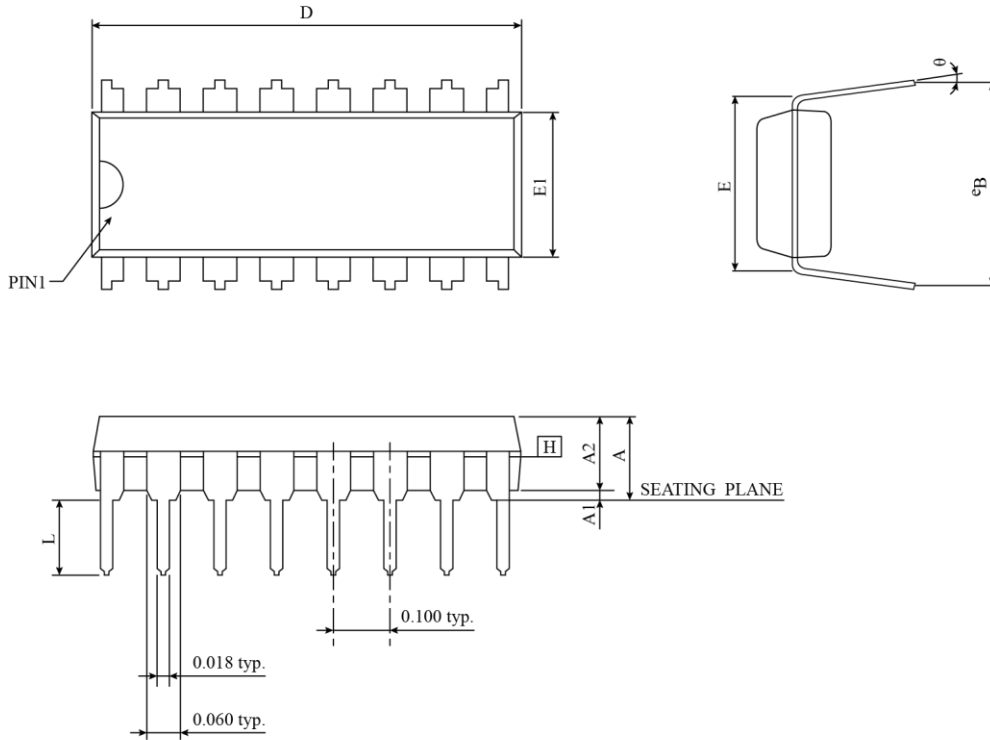
NOTES :

1. "D", "E1" DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010 INCH.
2. eB IS MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
3. POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION.
4. DISTANCE BETWEEN LEADS INCLUDING DAM BAR PROTRUSIONS TO BE .005 INCH MINIMUM.
5. DATUM PLANE H COINCIDENT WITH THE BOTTOM OF LEAD, WHERE LEAD EXITS BODY.

20-SOP Package Dimension


SYMBOL	DIMENSION IN MM		DIMENSION IN INCH	
	MIN	MAX	MIN	MAX
A	2.35	2.65	0.0926	0.1043
A1	0.10	0.30	0.0040	0.0118
B	0.33	0.51	0.013	0.020
C	0.23	0.32	0.0091	0.0125
D	12.60	13.00	0.4961	0.5118
E	10.00	10.65	0.394	0.491
E1	7.40	7.60	0.2914	0.2992
e	1.27 BSC		0.050 BSC	
h	0.25	0.75	0.010	0.029
L	0.40	1.27	0.016	0.050
θ	0°	8°	0°	8°
JEDEC	MS-013 (AC)			

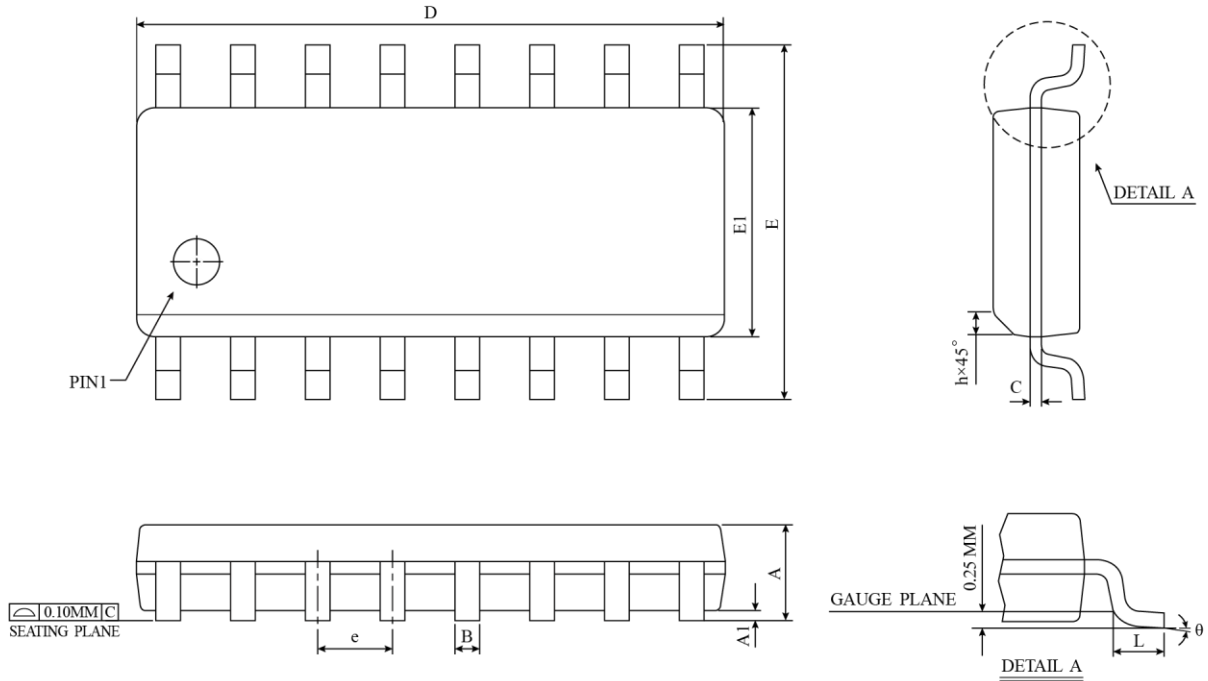
△ *NOTES : DIMENSION "D" DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL
NOT EXCEED 0.15 MM (0.006 INCH) PER SIDE.

16-DIP Package Dimension


SYMBOL	DIMENSION IN MM		DIMENSION IN INCH	
	MIN	MAX	MIN	MAX
A	-	4.369	-	0.172
A1	0.381	0.965	0.015	0.038
A2	3.175	3.429	0.125	0.135
D	18.669	19.685	0.735	0.775
E	7.620 BSC		0.300 BSC	
E1	6.223	6.477	0.245	0.255
L	2.921	3.810	0.115	0.150
eB	8.509	9.525	0.335	0.375
θ	0°	15°	0°	15°
JEDEC	MS-001 (BB)			

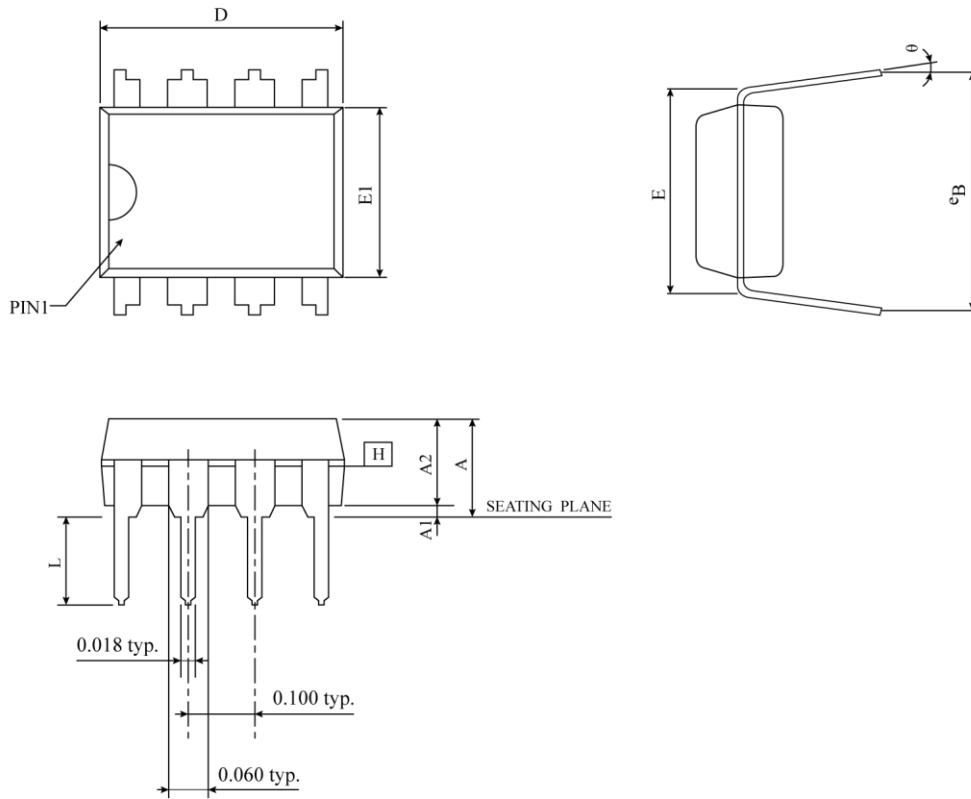
NOTES :

1. "D", "E1" DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010 INCH.
2. eB IS MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
3. POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION.
4. DISTANCE BETWEEN LEADS INCLUDING DAM BAR PROTRUSIONS TO BE .005 INCH MINIMUM.
5. DATUM PLANE H COINCIDENT WITH THE BOTTOM OF LEAD, WHERE LEAD EXITS BODY.

16-SOP Package Dimension


SYMBOL	DIMENSION IN MM		DIMENSION IN INCH	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.0532	0.0688
A1	0.10	0.25	0.0040	0.0098
B	0.33	0.51	0.013	0.020
C	0.19	0.25	0.0075	0.0098
D	9.80	10.00	0.3859	0.3937
E	5.80	6.20	0.2284	0.2440
E1	3.80	4.00	0.1497	0.1574
e	1.27 BSC		0.050 BSC	
h	0.25	0.50	0.0099	0.0196
L	0.40	1.27	0.016	0.050
θ	0°	8°	0°	8°
JEDEC	MS-012 (AC)			

△ *NOTES : DIMENSION "D" DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL
NOT EXCEED 0.15 MM (0.006 INCH) PER SIDE.

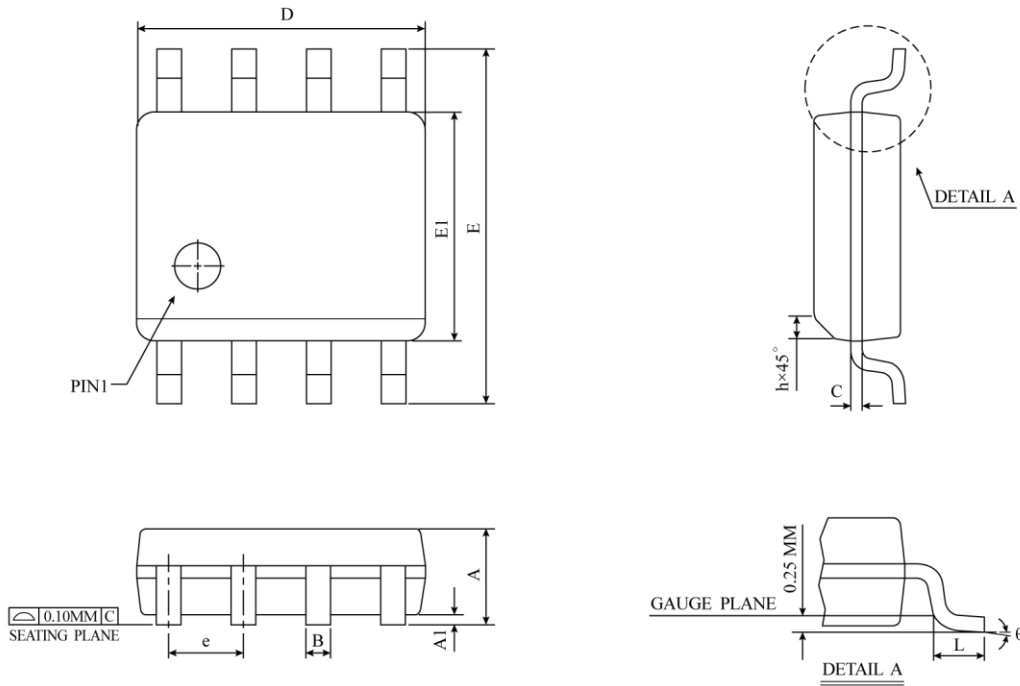
8-DIP (300mil) Package Dimension


SYMBOL	DIMENSION IN MM			DIMENSION IN INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	-	-	5.334	-	-	0.210
A1	0.381	-	-	0.015	-	-
A2	3.175	3.302	3.429	0.125	0.130	0.135
D	9.017	9.586	10.160	0.355	0.378	0.400
E	7.620 BSC			0.300 BSC		
E1	6.223	6.350	6.477	0.245	0.250	0.255
L	2.921	3.366	3.810	0.115	0.133	0.150
eB	8.509	9.017	9.525	0.335	0.355	0.375
θ	0°	7.5°	15°	0°	7.5°	15°
JEDEC	MS-001 (BA)					

NOTES :

1. "D" , "E1" DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010 INCH.
2. eB IS MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
3. POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION.
4. DISTANCE BETWEEN LEADS INCLUDING DAM BAR PROTRUSIONS TO BE .005 INCH MINIMUM.
5. DATUM PLANE \square COINCIDENT WITH THE BOTTOM OF LEAD, WHERE LEAD EXITS BODY.

8-SOP (150mil) Package Dimension



SYMBOL	DIMENSION IN MM			DIMENSION IN INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.35	1.55	1.75	0.0532	0.0610	0.0688
A1	0.10	0.18	0.25	0.0040	0.0069	0.0098
B	0.33	0.42	0.51	0.0130	0.0165	0.0200
C	0.19	0.22	0.25	0.0075	0.0087	0.0098
D	4.80	4.90	5.00	0.1890	0.1939	0.1988
E	5.80	6.00	6.20	0.2284	0.2362	0.2440
E1	3.80	3.90	4.00	0.1497	0.1536	0.1574
e	1.27 BSC			0.050 BSC		
h	0.25	0.38	0.50	0.0099	0.0148	0.0196
L	0.40	0.84	1.27	0.0160	0.0330	0.0500
θ	0°	4°	8°	0°	4°	8°
JEDEC	MS-012 (AA)					

⚠ * NOTES : DIMENSION " D " DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL
NOT EXCEED 0.15 MM (0.006 INCH) PER SIDE.